8-bit Proprietary Microcontroller

CMOS

F²MC-8L MB89490 Series

MB89497/498/F499/PV490

PRELIMINARY

■ DESCRIPTION

The MB89490 series has been developed as a general-purpose version of the F²MC*-8L family consisting of proprietary 8-bit single-chip microcontrollers.

In addition to a compact instruction set, the microcontroller contains a variety of peripheral functions such as 21-bit timebase timer, watch prescaler, PWM timer, 8/16-bit timer/counter, remote receiver control, LCD controller/driver, external interrupt 0 (edge), external interrupt 1 (level), 10-bit A/D converter, UART/SIO, SIO, I²C and watchdog timer reset.

The MB89490 series is designed suitable for compact disc/cassette tape/radio receiver controller as well as in a wide range of applications for consumer product.

*: F²MC stands for FUJITSU Flexible Microcontroller.

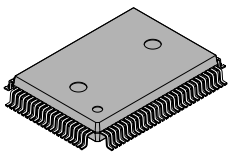
■ FEATURES

- Package used
  QFP package for MB89F499, MB89497,MB89498
  MQFP package for MB89PV490
- High speed operating capability at low voltage
- Minimum execution time: 0.32 µs/12.5MHz

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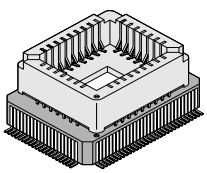
■ PACKAGE

100-pin Plastic QFP



(FTP-100P-M06)

100-pin Ceramic MQFP



(MQP-100C-P01)

(Continued)

- F²MC-8L family CPU core

  Instruction set optimized for controllers
  - Multiplication and division instructions
  - 16-bit arithmetic operations
  - Test and branch instructions
  - Bit manipulation instructions, etc.

- Clock
  Embedded PLL clock multiplication circuit for sub-clock
  Operating clock (PLL for sub-clock) can be selected four times of the sub-clock oscillation
- Six timers
  PWM timer x 2
  8/16-bit timer/counter x 2
  21-bit timebase timer
  Watch prescaler
- External interrupt
  Edge detection (selectable edge) : 8 channels
  Low level interrupt (wake-up function) : 8 channels
- 10-bit A/D converter (8 channels)
  10-bit successive approximation type
- UART/SIO
  Synchronous/asynchronous data transfer capability
- SIO
  Synchronous data transfer capability
- LCD controller/driver
  Max. 32 segments output x 4 commons
- I²C interface circuit
- Remote receiver circuit
- Low-power consumption mode
  Stop mode (oscillation stops so as to minimize the current consumption.)
  Sleep mode (CPU stops so as to reduce the current consumption to approx. 1/3 of normal.)
  Watch mode (everything except the watch prescaler stops so as to reduce the power comsumption to an extremely low level.)
  Sub-clock mode
- Watchdog timer reset
- I/O ports: max. 66channels

■ PRODUCT LINEUP

Parameter \ Part number	MB89497	MB89498	MB89F499	MB89PV490
Classification	Mass production products (mask ROM product)		FLASH	Piggy-back
ROM size	32K x 8-bit (internal ROM)	48K x 8-bit (internal ROM)	60K x 8-bit (internal FLASH)	60K x 8-bit (external ROM)*1
RAM size	1K x 8-bit	2K x 8-bit	2K x 8-bit	2K × 8-bit

*1 : Use MBM27C512 as the external ROM.

Parameter \ Part number	MB89497	MB89498	MB89F499	MB89PV490
CPU functions	Number of instructions : 136 Instruction bit length : 8 bits Instruction length : 1 to 3 bytes Data bit length : 1, 8, 16 bits Minimum execution time : 0.32 µs/12.5 MHz Minimum interrupt processing time : 2.88 µs/12.5 MHz			
Ports	I/O ports (CMOS) : 56 pins Input ports (CMOS) : 2 pins N-channel open drain I/O ports : 8 pins Total : 66 pins			
21-bit timebase timer	Interrupt period (0.66 ms, 2.6 ms, 21.0 ms, 335.5 ms) at 12.5 MHz			
Watchdog timer	Reset period (167.8 ms to 335.5 ms) at 12.5 MHz.			
PWM timer 0,1	8-bit reload timer operation (supports square wave output, operating clock period: 1, 8, 16, 64 t_{inst},) 8-bit resolution PWM operation			
8/16-bit timer/ counter 00, 01	Can be operated either as a 2-channel 8-bit timer/counter (timer 00 and timer 01, each with its own independent operating clock cycle), or as one 16-bit timer/counter In timer 00 or 16-bit timer/counter operation, event counter operation (external clock-triggered) and square wave output capability			
8/16-bit timer/ counter 10, 11	Can be operated either as a 2-channel 8-bit timer/counter (timer 10 and timer 11, each with its own independent operating clock cycle), or as one 16-bit timer/counter In timer 10 or 16-bit timer/counter operation, event counter operation (external clock-triggered) and square wave output capability			
External interrupt 0 (edge)	8 independent channels (selectable edge, interrupt vector, request flag)			
External interrupt 1 (level)	8 channels (low level interrupt)			
A/D converter	10-bit resolution × 8 channels A/D conversion function (conversion time: 38 t_{inst}) Supports repeated activation by internal clock			
LCD controller/driver	Common output : 4 (max.) Segment output : 32 (max.) Bias power supply pins : 3 LCD display RAM size : 32 × 4 bits			
UART/SIO	Synchronous/asynchronous data transfer capability (Max. baud rate: 97.656 Kbps at 12.5 MHz) (7 and 8 bits with parity bit; 8 and 9 bits without parity bit)			
SIO	8-bit serial I/O with LSB first/MSB first selectability One clock selectable from four operation clock (one external shift clock, three internal shift clock: 0.64µs, 2.56µs, 10.24µs at 12.5MHz)			
I²C*1	1 channel Use a 2-wire protocol to communicate with other device			
Remote receiver	Selectable maximum noise width removal Reversible input polarity			
Standby mode	Sleep mode, stop mode, watch mode, sub-clock mode			
Process	CMOS			
Operating voltage	2.2V ~ 3.6V		2.7V ~ 3.6V	2.7V ~ 3.6V

*1 : I²C is complied to Philips I²C specification.

■ PACKAGE AND CORRESPONDING PRODUCTS

Part number / Package	MB89497/498	MB89F499	MB89PV490
FPT-100P-M06	O	O	X
MQP-100C-P01	X	X	O

O : Availabe
X : Not available

■ DIFFERENCES AMONG PRODUCTS

1. Memory Size

Before evaluating using the piggyback product, verify its differences from the product that will actually be used. Take particular care on the following point:

- The stack area is set at the upper limit of the RAM.

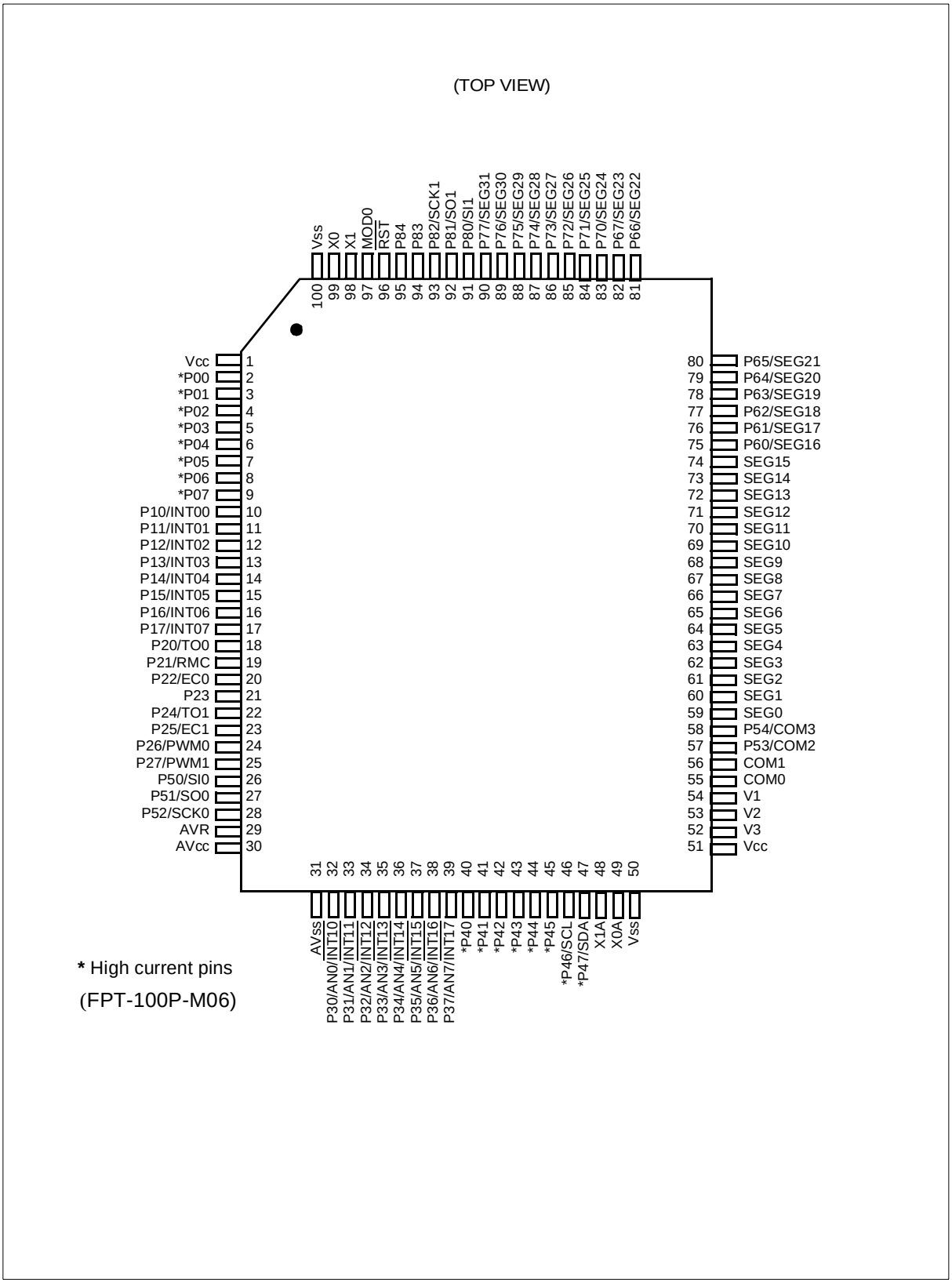
2. Current Consumption

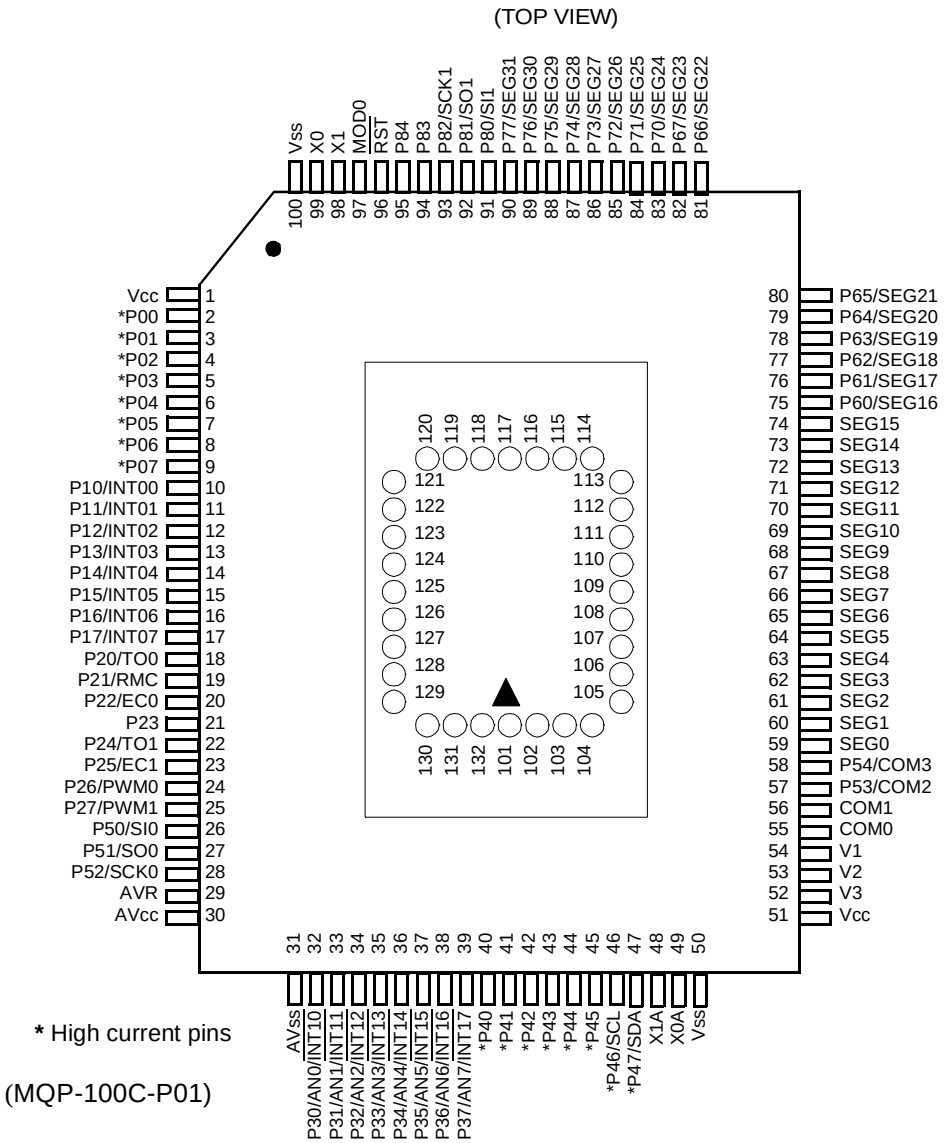
- For the MB89PV490 the current consumed by the EPROM mounted in the piggy-back socket is needed to be included.
- When operating at low speed, the current consumed by the FLASH product is greater than that for the mask ROM product. However, the current consumption is roughly the same in sleep and stop mode.
- For more information, see “■ Electrical Characteristics.”

3. Oscillation Stabilization Time after Power-on Reset

- For MB89PV490 and MB89F499, the power-on stabilization time cannot be selected.
- For MB89497 and MB89498, the power-on stabilization time can be selected.
- For more information, please refer to “■ Mask Option”.

■ PIN ASSIGNMENT





Pin assignment on package top (MB89PV490 only)

Pin no.	Pin name	Pin no.	Pin name	Pin no.	Pin name	Pin no.	Pin name
101	N.C.	109	A2	117	N.C.	125	$\overline{OE}$
102	A15	110	A1	118	O4	126	N.C.
103	A12	111	A0	119	O5	127	A11
104	A7	112	N.C.	120	O6	128	A9
105	A6	113	O1	121	O7	129	A8
106	A5	114	O2	122	O8	130	A13
107	A4	115	O3	123	$\overline{CE}$	131	A14
108	A3	116	V_{SS}	124	A10	132	V_{CC}

N.C.: As connected internally, do not use.

■ PIN DESCRIPTION

Pin number MQFP*1/QFP*2	Pin name	I/O circuit type	Function
99	X0	A	Connection pins for a crystal or other oscillator. An external clock can be connected to X0. In this case, leave X1 open.
98	X1		
49	X0A	A	Connection pins for a crystal or other oscillator. An external clock can be connected to X0A. In this case, leave X1A open.
48	X1A		
97	MOD0	B	Input pin for setting the memory access mode. Connect directly to V_{SS}.
95, 94	P84,P83	J	General-purpose CMOS Input port.
96	$\overline{RST}$	C	Reset I/O pin. The pin is an N-ch open-drain type with pull-up resistor and a hysteresis input. The pin outputs an “L” level when an internal reset request is present. Inputting an “L” level initializes internal circuits.
2~9	P00 ~ P07	D	General-purpose CMOS I/O port.
10~17	P10/INT00 ~ P17/INT07	E	General-purpose CMOS I/O port. The pin is shared with external interrupt 0 input.
18	P20/TO0	F	General-purpose CMOS I/O port. The pin is shared with 8/16-bit timer/counter 00, 01 output.
19	P21/RMC	E	General-purpose CMOS I/O port. The pin is shared with remote receiver input.
20	P22/EC0	E	General-purpose CMOS I/O port. The pin is shared with 8/16-bit timer/counter 00, 01 input.
21	P23	F	General-purpose CMOS I/O port.
22	P24/TO1	F	General-purpose CMOS I/O port. The pin is shared with 8/16-bit timer/counter 10, 11 output.
23	P25/EC1	E	General-purpose CMOS I/O port. The pin is shared with 8/16-bit timer/counter 10,11 input.
24	P26/PWM0	F	General-purpose CMOS I/O port. The pin is shared with PWM0 output.
25	P27/PWM1	F	General-purpose CMOS I/O port. The pin is shared with PWM1 output.
32 ~ 39	P30/AN0/$\overline{INT10}$ ~ P37/AN7/$\overline{INT17}$	G	General-purpose CMOS I/O port. The pin is shared with external interrupt 1 input and A/D converter input.
40 ~ 45	P40~P45	H	General-purpose N-ch open-drain I/O port.
46	P46/SCL	H	General-purpose N-ch open-drain I/O port. The pin is shared with I2C clock I/O.
47	P47/SDA	H	General-purpose N-ch open-drain I/O port. The pin is shared with I2C data I/O.
26	P50/SI0	E	General-purpose CMOS I/O port. The pin is shared with SIO data input.
27	P51/SO0	F	General-purpose CMOS I/O port. The pin is shared with SIO data output.
28	P52/SCK0	E	General-purpose CMOS I/O port. The pin is shared with SIO clock I/O.

(Continued)

Pin number MQFP*1/QFP*2	Pin name	I/O circuit type	Function
57	P53/COM2	F / I	General-purpose CMOS I/O port. The pin is shared with the LCD common output.
58	P54/COM3	F / I	General-purpose CMOS I/O port. The pin is shared with the LCD common output.
75 ~ 82	P60/SEG16 ~ P67/SEG23	F / I	General-purpose CMOS I/O port. The pin is shared with LCD segment output.
83 ~ 90	P70/SEG24 ~ P77/SEG31	F / I	General-purpose CMOS I/O port. The pin is shared with LCD segment output.
91	P80/SI1	E	General-purpose CMOS I/O port. The pin is shared with UART/SIO data input.
92	P81/SO1	F	General-purpose CMOS I/O port. The pin is shared with UART/SIO data output.
93	P82/SCK1	E	General-purpose CMOS I/O port. The pin is shared with UART/SIO clock I/O.
59 ~ 74	SEG0 ~ SEG15	I	LCD segment output-only pin.
55 ~ 56	COM0 ~ COM1	I	LCD common output-only pin.
54, 53, 52	V1 to V3	—	LCD driving power supply pin.
1,51	V_{CC}	—	Power supply pin.
50,100	V_{SS}	—	Power supply pin (GND).
30	AV_{CC}	—	A/D converter power supply pin.
29	AVR	—	A/D converter reference voltage input pin.
31	AV_{SS}	—	A/D converter power supply pin. Use at the same voltage level as V_{SS}.

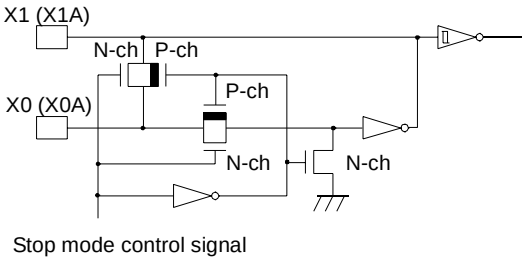
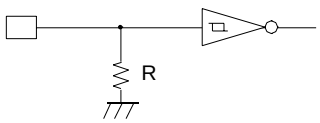
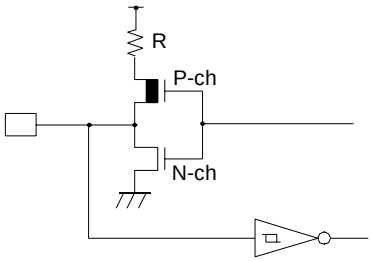
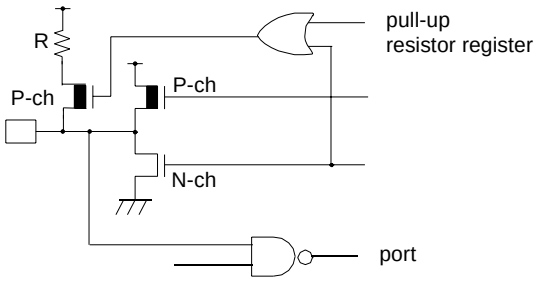
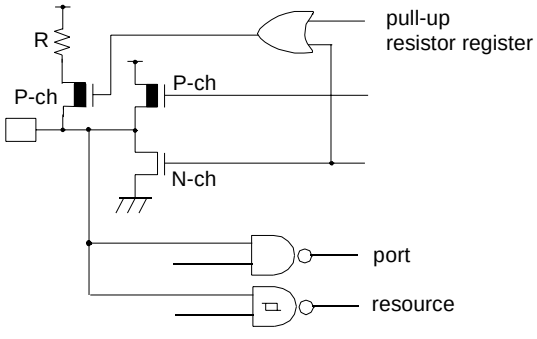
*1: MQP-100C-P01
*2: FPT-100P-M06

• External EPROM Socket (MB89PV490 only)

Pin number MQFP*1	Pin name	I/O	Function
102 131 130 103 127 124 128 129 104 105 106 107 108 109 110 111	A15 A14 A13 A12 A11 A10 A9 A8 A7 A6 A5 A4 A3 A2 A1 A0	O	Address output pins.
122 121 120 119 118 115 114 113	O8 O7 O6 O5 O4 O3 O2 O1	I	Data input pins.
101 112 117 126	N.C.	—	Internally connected pins. Always leave open.
116	V_{SS}	O	Power supply pin (GND).
123	$\overline{CE}$	O	Chip enable pin for the EPROM. Outputs “H” in standby mode.
125	$\overline{OE}$	O	Output enable pin for the EPROM. Always outputs “L”.
132	V_{CC}	O	Power supply pin for the EPROM.

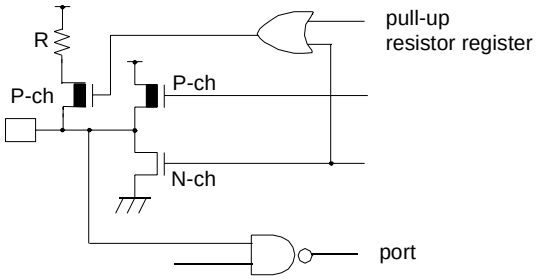
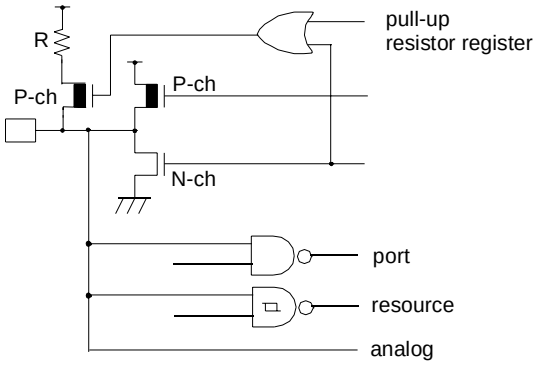
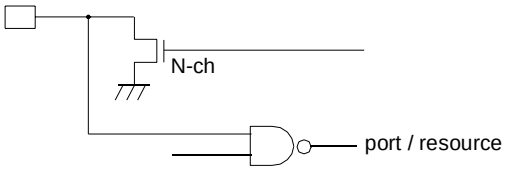
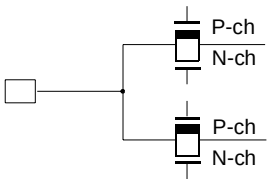
*1: MQP-100C-P01

■ I/O CIRCUIT TYPE

Circuit Class	Circuit	Remarks
A		• Main/Sub-clock circuit
B		• Hysteresis input (CMOS input in MB89F499) • The pull-down resistor (not available in MB89F499) Approx. 50kΩ
C		• The pull-up resistor (P-channel) Approx. 50 kΩ • Hysteresis input
D		• CMOS output • IOH=-4mA, IOL=12mA • CMOS input • Selectable pull-up resistor Approx. 50 kΩ
E		• CMOS output • IOH=-2mA, IOL=4mA • CMOS port input • Hysteresis resource input • Selectable pull-up resistor Approx. 50 kΩ

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F		• CMOS output • IOH=-2mA, IOL=4mA • CMOS input • Selectable pull-up resistor Approx. 50 kΩ
G		• CMOS output • IOH=-2mA, IOL=4mA • CMOS port input • Automotive (VIH=0.85Vcc, VIL=0.5Vcc) resource input • Analog input • Selectable pull-up resistor Approx. 50 kΩ
H		• N-ch open-drain output • IOL=15mA • CMOS port input • CMOS resource input • 5V tolerance
I		• LCD segment output
J		• CMOS input

■ HANDLING DEVICES

1. Preventing Latch-up

Latch-up may occur on CMOS ICs if voltage higher than V_{CC} or lower than V_{SS} is applied to input and output pins other than medium- to high-voltage pins or if higher than the voltage which shows on "1. Absolute Maximum Ratings" in "■ Electrical Characteristics" is applied between V_{CC} and V_{SS}.

When latch-up occurs, power supply current increases rapidly and might thermally damage elements. When using, take great care not to exceed the absolute maximum ratings.

Also, take care to prevent the analog power supply (AV_{CC} and AVR), and analog input from exceeding the digital power supply (V_{CC}) when the analog system power supply is turned on and off.

2. Treatment of Unused Input Pins

Leaving unused input pins open could cause malfunctions. They should be connected to a pull-up or pull-down resistor.

3. Treatment of Power Supply Pins on Microcontrollers with A/D

Connect to be $AV_{CC} = V_{CC}$ and $AV_{SS} = AVR = V_{SS}$ even if the A/D is not in use.

4. Treatment of N.C. Pins

Be sure to leave (internally connected) N.C. pins open.

5. Power Supply Voltage Fluctuations

Although V_{CC} power supply voltage is assured to operate within the rated range, a rapid fluctuation of the voltage could cause malfunctions, even if it occurs within the rated range. Stabilizing voltage supplied to the IC is therefore important. As stabilization guidelines, it is recommended to control power so that V_{CC} ripple fluctuations (P-P value) will be less than 10% of the standard V_{CC} value at the commercial frequency (50 to 60 Hz) and the transient fluctuation rate will be less than 0.1 V/ms at the time of a momentary fluctuation such as when power is switched.

6. Precautions when Using an External Clock

Even when an external clock is used, oscillation stabilization time is required for power-on reset and wake-up from stop mode.

7. Treatment of Unused dedicated LCD pins

When dedicated LCD pins are not in use, keep them open.

■ PROGRAMMING AND ERASING FLASH MEMORY ON THE MB89F499

1. Flash Memory

The flash memory is located between 1000_H and $FFFF_H$ in the CPU memory map and incorporates a flash memory interface circuit that allows read access and program access from the CPU to be performed in the same way as mask ROM. Programming and erasing flash memory is also performed via the flash memory interface circuit by executing instructions in the CPU. This enables the flash memory to be updated in place under the control of the CPU, providing an efficient method of updating program and data.

2. Flash Memory Features

- 60 K byte × 8-bit configuration (16 K + 8 K + 8 K + 28 K sectors)
- Automatic programming algorithm (Embedded algorithm* : Equivalent to MBM29LV200)
- Includes an erase pause and restart function
- Data polling and toggle bit for detection of program/erase completion
- Detection of program/erase completion via CPU interrupt
- Compatible with JEDEC-standard commands
- Sector Protection (sectors can be combined in any combination)
- No. of program/erase cycles : 10,000 (Min)

*: Embedded Algorithm is a trademark of Advanced Micro Devices.

3. Procedure for Programming and Erasing Flash Memory

Programming and reading flash memory cannot be performed at the same time. Accordingly, to program or erase flash memory, the program must first be copied from flash memory to RAM so that programming can be performed without program access from flash memory.

4. Flash Memory Register

- Control status register (FMCS)

Address	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Initial value
$007A_H$	INTE	RDYINT	WE	RDY	Reserved	Reserved	—	Reserved	$000X00\text{-}0_B$
	R/W	R/W	R/W	R	R/W	R/W	—	R/W	

5. Sector Configuration

The table below shows the sector configuration of flash memory and lists the addresses of each sector for both during CPU access a flash memory programming.

- Sector configuration of flash memory

Flash Memory	CPU Address	Programmer Address*
16 K bytes	$FFFF_H$ to $C000_H$	$1FFFF_H$ to $1C000_H$
8 K bytes	$BFFF_H$ to $A000_H$	$1BFFF_H$ to $1A000_H$
8 K bytes	$9FFF_H$ to 8000_H	$19FFF_H$ to 18000_H
28 K bytes	$7FFF_H$ to 1000_H	$17FFF_H$ to 11000_H

* : Programmer address

The programmer address is the address to be used instead of the CPU address when programming data from a parallel flash memory programmer. Use the programmer address on programming or erasing using a general purpose parallel programmer.

6. ROM Programmer Adaptor and Recommended ROM Programmers

Part number	Package	Adaptor Part No.	Recommended Programmer Manufacturer and Model
		Sun Hayato Co. Ltd.	Ando Denki Co. Ltd.
MB89F499PF	FPT-100P-M06	TBD	AF9708 (ver 1.60 or later) AF9709 (ver 1.60 or later)

* Enquiries

Sunhayato Co. Ltd. : FAX +81-3-5396-9106

Ando Denki Co. Ltd. : TEL +81-44-549-7300

■ PROGRAMMING TO THE EPROM WITH PIGGYBACK/EVALUATION DEVICE

1. EPROM for Use

MBM27C512-20TV

2. Programming Socket Adapter

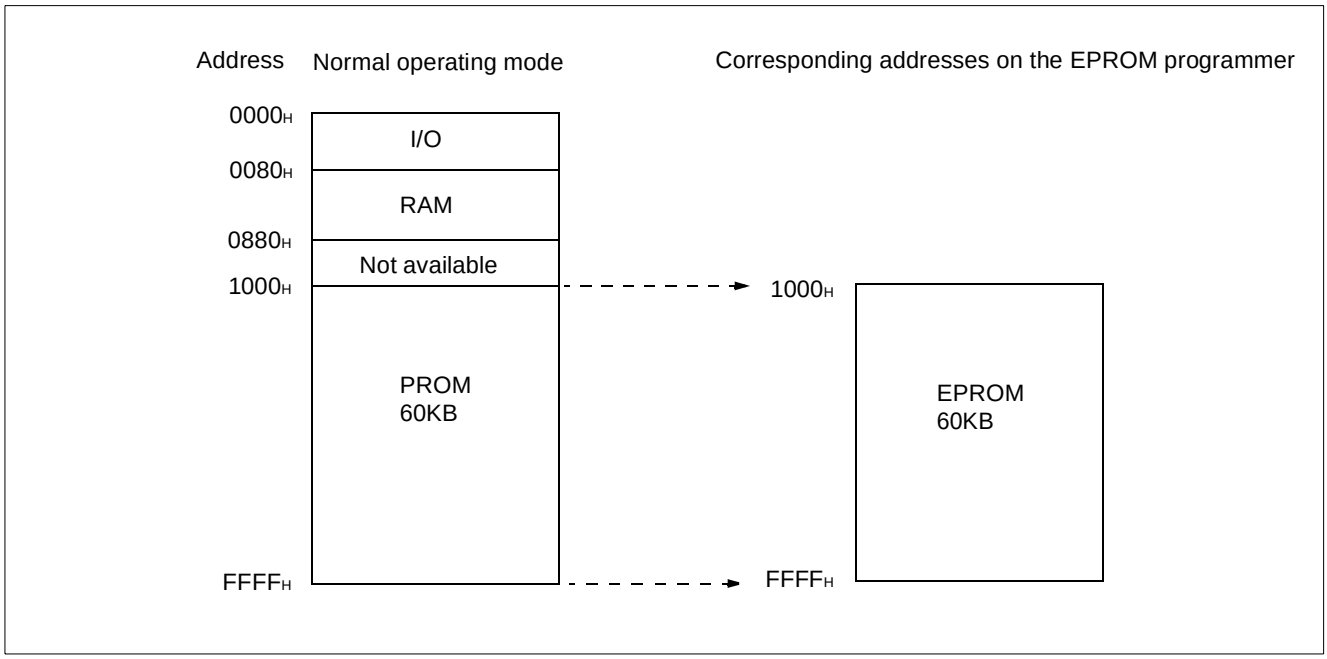
To program to the PROM using an EPROM programmer, use the socket adapter (manufacturer: Sun Hayato Co., Ltd.) listed below.

Package	Adapter socket part number
LCC-32 (Rectangle)	ROM-32LC-28DP-YG

Inquiry: Sun Hayato Co., Ltd.: TEL 81-3-3986-0403

3. Memory Space

Memory space in each mode is shown in the diagram below.



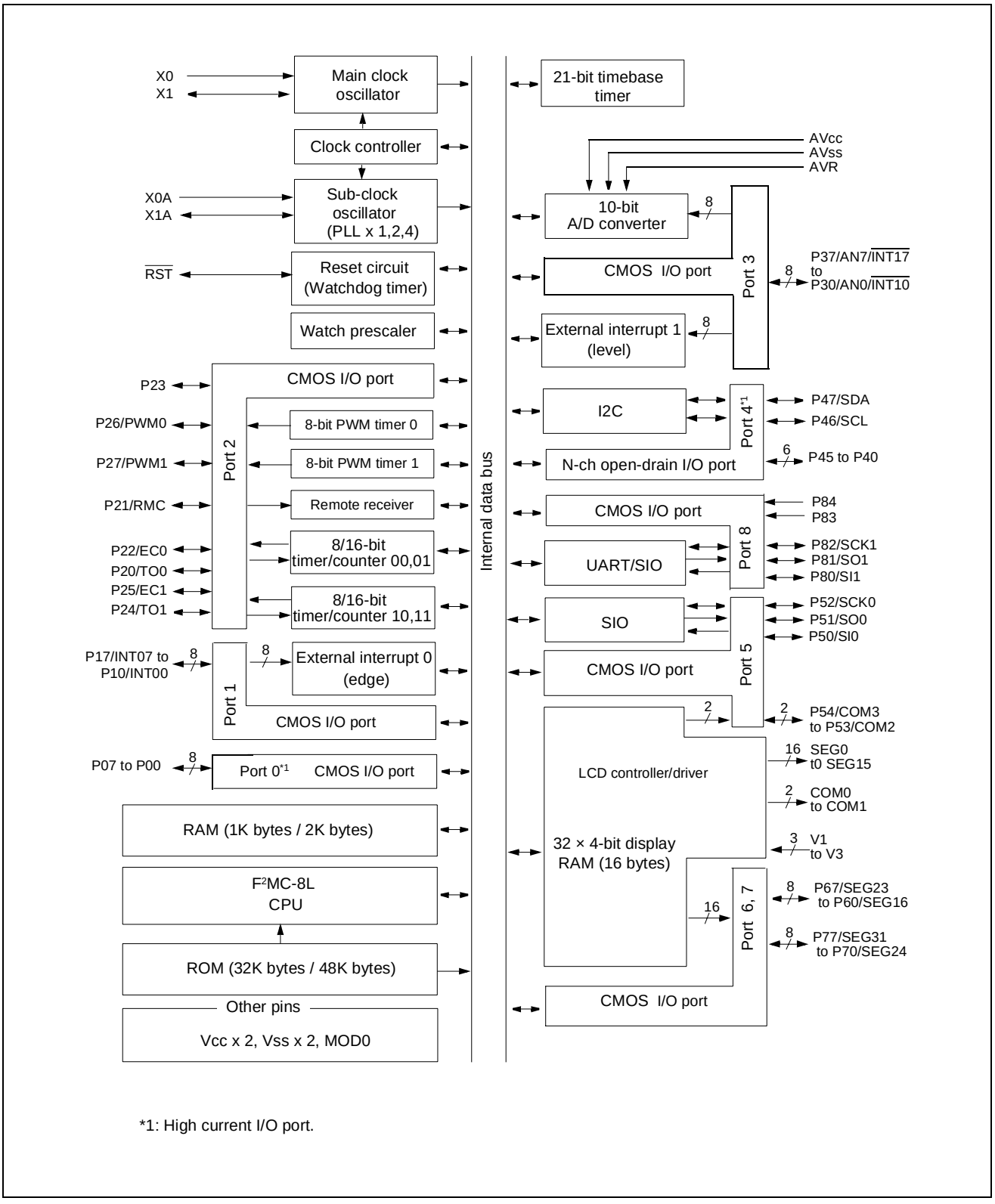
4. Programming to the EPROM

(1) Set the EPROM programmer to the MBM27C512.

(2) Load program data into the EPROM programmer at 1000_H to $FFFF_H$.

(3) Program to 1000_H to $FFFF_H$ with the EPROM programmer.

■ Block Diagram



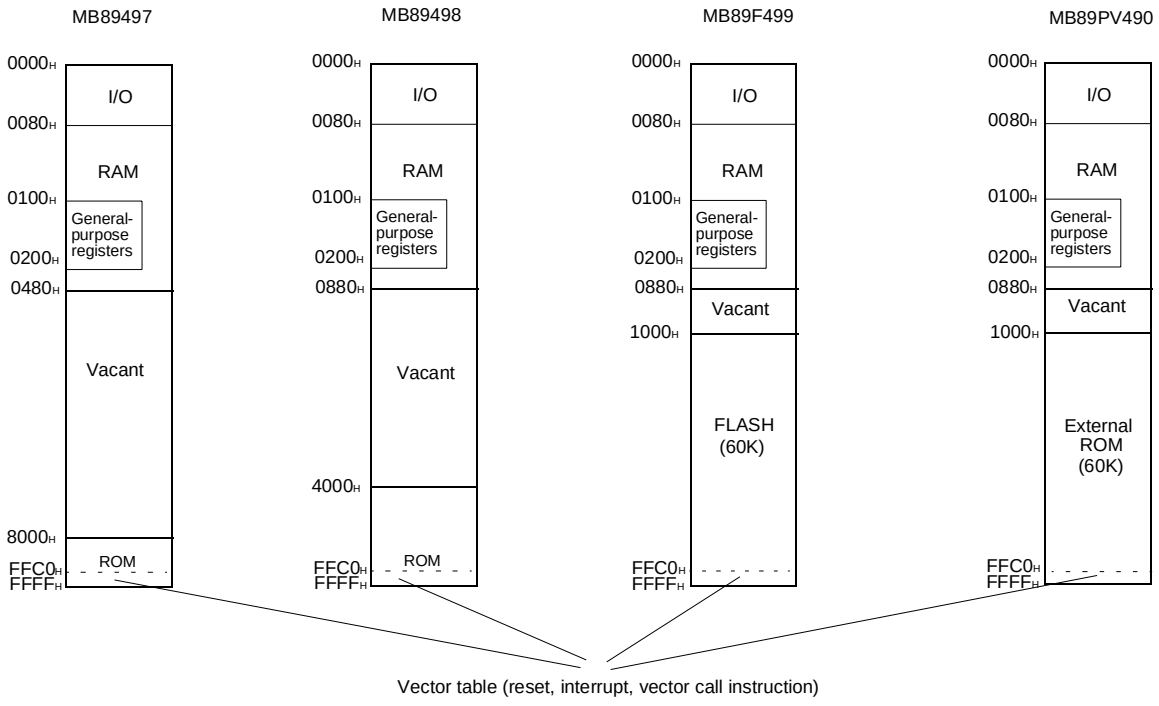
*1: High current I/O port.

■ CPU CORE

1. Memory Space

The microcontrollers of the MB89490 series offer a memory space of 64 Kbytes for storing all of I/O, data, and program areas. The I/O area is located the lowest address. The data area is provided immediately above the I/O area. The data area can be divided into register, stack, and direct areas according to the application. The program area is located at exactly the opposite end, that is, near the highest address. Provide the tables of interrupt reset vectors and vector call instructions toward the highest address within the program area. The memory space of the MB89490 series is structured as illustrated below.

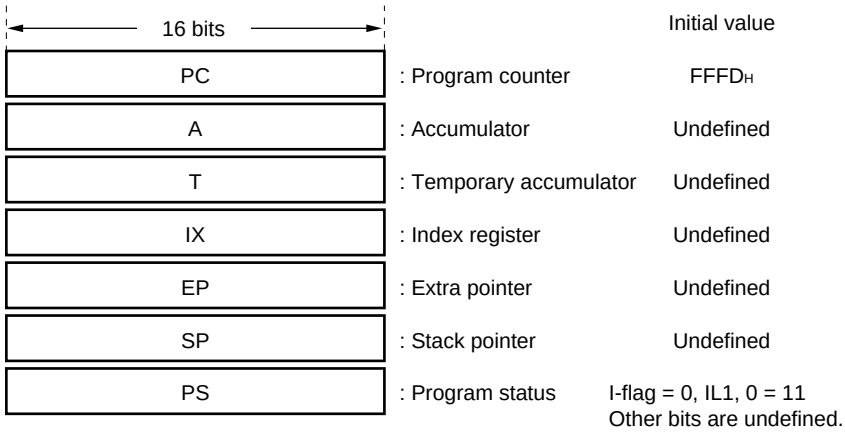
Memory Space



2. Registers

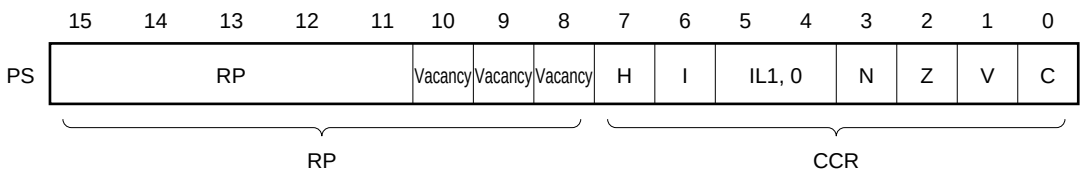
The F²MC-8L family has two types of registers; dedicated registers in the CPU and general-purpose registers in the memory. The following registers are provided:

Program counter (PC):	A 16-bit register for indicating instruction storage positions.
Accumulator (A):	A 16-bit temporary register for storing arithmetic operations, etc. When the instruction is an 8-bit data processing instruction, the lower byte is used.
Temporary accumulator (T):	A 16-bit register for performing arithmetic operations with the accumulator. When the instruction is an 8-bit data processing instruction, the lower byte is used.
Index register (IX):	A 16-bit register for index modification.
Extra pointer (EP):	A 16-bit pointer for indicating a memory address.
Stack pointer (SP):	A 16-bit register for indicating a stack area.
Program status (PS):	A 16-bit register for storing a register pointer, a condition code.



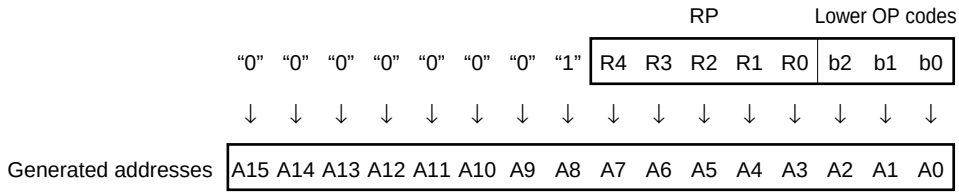
The PS can further be divided into higher 8 bits for use as a register bank pointer (RP) and the lower 8 bits for use as a condition code register (CCR). (See the diagram below.)

Structure of the Program Status Register



The RP indicates the address of the register bank currently in use. The relationship between the pointer contents and the actual address is based on the conversion rule illustrated below.

Rule for Conversion of Actual Addresses of the General-purpose Register Area



The CCR consists of bits indicating the results of arithmetic operations and the contents of transfer data and bits for control of CPU operations at the time of an interrupt.

H-flag: Set to "1" when a carry or a borrow from bit 3 to bit 4 occurs as a result of an arithmetic operation. Clear to "0" otherwise. This flag is for decimal adjustment instructions.

I-flag: Interrupt is allowed when this flag is set to "1". Interrupt is prohibited when the flag is set to "0". Clear to "0" when reset.

IL1, 0: Indicates the level of the interrupt currently allowed. Processes an interrupt only if its request level is higher than the value indicated by this bit.

IL1	IL0	Interrupt level	Priority
0	0	1	High
0	1		
1	0	2	
1	1	3	Low = no interrupt

N-flag: Set to "1" if the MSB is set to "1" as the result of an arithmetic operation. Clear to "0" otherwise.

Z-flag: Set to "1" when an arithmetic operation results in "0". Clear to "0" otherwise.

V-flag: Set to "1" if a signed numeric value overflows because of an arithmetic calculation. Clear to "0" if the overflow does not occur.

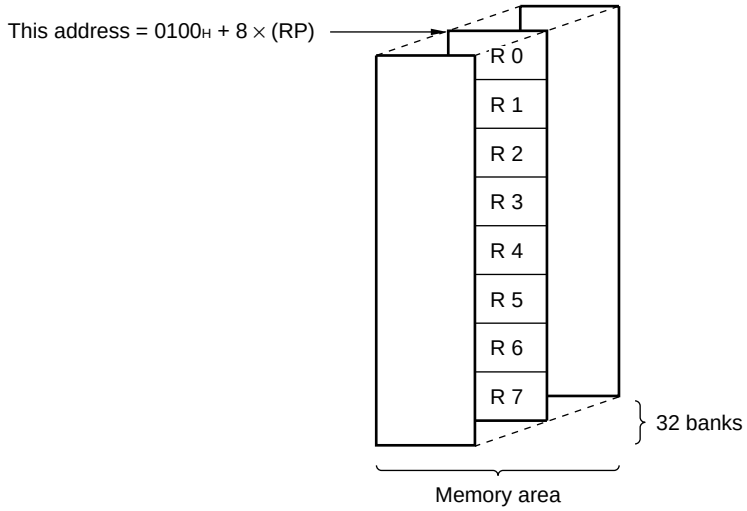
C-flag: Set to "1" when a carry or a borrow from bit 7 occurs as a result of an arithmetic operation. Clear to "0" otherwise. Set to the shift-out value in the case of a shift instruction.

The following general-purpose registers are provided:

General-purpose registers: An 8-bit register for storing data

The general-purpose registers are 8 bits and located in the register banks of the memory. One bank contains eight registers. Up to a total of 32 banks can be used on the MB89490 series. The bank currently in use is indicated by the register bank pointer (RP).

Register Bank Configuration



■ I/O MAP

Address	Register name	Register description	Read/Write	Initial value
00H	PDR0	Port 0 data register	R/W	XXXXXXXXB
01H	DDR0	Port 0 data direction register	W*	00000000B
02H	PDR1	Port 1 data register	R/W	XXXXXXXXB
03H	DDR1	Port 1 data direction register	W*	00000000B
04H	PDR2	Port 2 data register	R/W	00000000B
05H	(Reserved)			
06H	DDR2	Port 2 data direction register	R/W	00000000B
07H	SYCC	System clock control register	R/W	X-1MM100B
08H	STBC	Standby control register	R/W	00010XXXB
09H	WDTC	Watchdog timer control register	W*	0---XXXXB
0AH	TBTC	Timebase timer control register	R/W	00---000B
0BH	WPCR	Watch prescaler control register	R/W	00--0000B
0CH	PDR3	Port 3 data register	R/W	XXXXXXXXB
0DH	DDR3	Port 3 data direction register	R/W	00000000B
0EH	RSFR	Reset flag register	R	XXXX----B
0FH	PDR4	Port 4 data register	R/W	11111111B
10H	PDR5	Port 5 data register	R/W	---XXXXXB
11H	DDR5	Port 5 data direction register	R/W	---00000B
12H	PDR6	Port 6 data register	R/W	XXXXXXXXB
13H	DDR6	Port 6 data direction register	R/W	00000000B
14H	PDR7	Port 7 data register	R/W	XXXXXXXXB
15H	DDR7	Port 7 data direction register	R/W	00000000B
16H	PDR8	Port 8 data register	R/W	---XXXXXB
17H	DDR8	Port 8 data direction register	R/W	---00000B
18H	EIC0	External interrupt 0 control register 0	R/W	00000000B
19H	EIC1	External interrupt 0 control register 1	R/W	00000000B
1AH	EIC2	External interrupt 0 control register 2	R/W	00000000B
1BH	EIC3	External interrupt 0 control register 3	R/W	00000000B
1CH	EIE1	External interrupt 1 enable register	R/W	00000000B
1DH	EIF1	External interrupt 1 flag register	R/W	-------0B
1EH	SMR	Serial mode register	R/W	00000000B
1FH	SDR	Serial data register	R/W	XXXXXXXXB
20H	T01CR	Timer 01 control register	R/W	000000X0B
21H	T00CR	Timer 00 control register	R/W	000000X0B
22H	T01DR	Timer 01 data register	R/W	XXXXXXXXB
23H	T00DR	Timer 00 data register	R/W	XXXXXXXXB
24H	T11CR	Timer 11 control register	R/W	000000X0B
25H	T10CR	Timer 10 control register	R/W	000000X0B

(Continued)

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Address	Register name	Register description	Read/Write	Initial value
26_H	T11DR	Timer 11 data register	R/W	$XXXXXXXX_B$
27_H	T10DR	Timer 10 data register	R/W	$XXXXXXXX_B$
28_H	ADER	A/D input enable register	R/W	11111111_B
29_H	ADC0	A/D control register 0	R/W	$-00000X0_B$
$2A_H$	ADC1	A/D control register 1	R/W	-0000001_B
$2B_H$	ADDH	A/D data register (Upper byte)	R	$------XX_B$
$2C_H$	ADDL	A/D data register (Lower byte)	R	$XXXXXXXX_B$
$2D_H$	CNTR0	PWM 0 timer control register	R/W	$0-000000_B$
$2E_H$	COMR0	PWM 0 timer compare register	W*	$XXXXXXXX_B$
$2F_H$	SMC0	UART/SIO serial mode control register	R/W	00000000_B
30_H	SMC1	UART/SIO serial mode control register	R/W	00000000_B
31_H	SSD	UART/SIO serial status/data register	R/W	$00001---_B$
32_H	SIDR/SODR	UART/SIO serial data register	R/W	$XXXXXXXX_B$
33_H	SRC	UART/SIO serial rate control register	R/W	$XXXXXXXX_B$
34_H	CNTR1	PWM 1 timer control register	R/W	$0-000000_B$
35_H	COMR1	PWM 1 timer compare register	W*	$XXXXXXXX_B$
36_H	IBSR	I^2C bus status register	R	00000000_B
37_H	IBCR	I^2C bus control register	R/W	00000000_B
38_H	ICCR	I^2C clock control register	R/W	$000XXXXX_B$
39_H	IADR	I^2C address register	R/W	$XXXXXXXX_B$
$3A_H$	IDAR	I^2C data register	R/W	$XXXXXXXX_B$
$3B_H$	PLLCR	Sub PLL control register	R/W	$----0000_B$
$3C_H$ to $3F_H$	(Reserved)			
40_H	RMN	Remote control counter register	R	$XXXXXXXX_B$
41_H	RMC	Remote control control register	R/W	00000000_B
42_H	RMS	Remote control status register	R/W	$0X000001_B$
43_H	RMD	Remote control FIFO data register	R	$X----XXX_B$
44_H	RMCD0	Remote control compare register 0	R/W	11111111_B
45_H	RMCD1	Remote control compare register 1	R/W	11111111_B
46_H	RMCD2	Remote control compare register 2	R/W	11111111_B
47_H	RMCD3	Remote control compare register 3	R/W	11111111_B
48_H	RMCD4	Remote control compare register 4	R/W	11111111_B
49_H	RMCD5	Remote control compare register 5	R/W	11111111_B
$4A_H$	RMCI	Remote interrupt register	R/W	$-110-000_B$
$4B_H$ to $5D_H$	(Reserved)			
$5E_H$	LOCR	LCD controller output control register	R/W	-0000000_B
$5F_H$	LCD	LCD controller control register	R/W	00010000_B
60_H to $6F_H$	VRAM	LCD data RAM	R/W	$XXXXXXXX_B$
70_H	PURC0	Port 0 pull up resistor control register	R/W	11111111_B
71_H	PURC1	Port 1 pull up resistor control register	R/W	11111111_B

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Address	Register name	Register description	Read/Write	Initial value
72H	PURC2	Port 2 pull up resistor control register	R/W	11111111B
73H	PURC3	Port 3 pull up resistor control register	R/W	11111111B
74H	PURC5	Port 5 pull up resistor control register	R/W	---11111B
75H	PURC6	Port 6 pull up resistor control register	R/W	11111111B
76H	PURC7	Port 7 pull up resistor control register	R/W	11111111B
77H	PURC8	Port 8 pull up resistor control register	R/W	-----111B
78H to 79H	(Reserved)			
7AH	FMCS	Flash memory control status registger	R/W	000X00-0B
7BH	ILR1	Interrupt level setting register 1	W*	11111111B
7CH	ILR2	Interrupt level setting register 2	W*	11111111B
7DH	ILR3	Interrupt level setting register 3	W*	11111111B
7EH	ILR4	Interrupt level setting register 4	W*	11111111B
7FH	(Reserved)			

* Bit manipulation instruction cannot be used.

- **Read/write access symbols**

R/W : Readable and writable
R : Read-only
W : Write-only

- **Initial value symbols**

0: The initial value of this bit is “0”.
1: The initial value of this bit is “1”.
X: The initial value of this bit is undefined.
- : Unused bit.
M: The initial value of this bit is determined by mask option.

■ ELECTRICAL CHARACTERISTICS

1. Absolute Maximum Ratings

(AV_{SS} = V_{SS} = 0.0 V)

Parameter	Symbol	Value		Unit	Remarks
		Min.	Max.		
Power supply voltage	V_{CC} AV_{CC}	V_{SS} – 0.3	V_{SS} + 4.0	V	AV_{CC} must be equal to V_{CC}
	AVR	V_{SS} – 0.3	V_{SS} + 4.0	V	
LCD power supply voltage	V1 to V3	V_{SS} – 0.3	V_{CC}	V	
Input voltage	V_I	V_{SS} – 0.3	V_{CC} + 0.3	V	other than P40~P47
		V_{SS} – 0.3	V_{SS} + 6.0	V	P40~P47 in MB89PV490, MB89497/498
		V_{SS} – 0.3	V_{SS} + 5.5	V	P40~P47 in MB89F499
Output voltage	V_O	V_{SS} – 0.3	V_{CC} + 0.3	V	
“L” level maximum output current	I_{OL}	—	15	mA	
“L” level average output current	I_{OLAV}	—	4	mA	Average value (operating current × operating rate)
“L” level total maximum output current	$\sum I_{OL}$	—	100	mA	
“L” level total average output current	$\sum I_{OLAV}$	—	40	mA	Average value (operating current × operating rate)
“H” level maximum output current	I_{OH}	—	–15	mA	
“H” level average output current	I_{OHAV}	—	–4	mA	Average value (operating current × operating rate)
“H” level total maximum output current	$\sum I_{OH}$	—	–50	mA	
“H” level total average output current	$\sum I_{OHAV}$	—	–20	mA	Average value (operating current × operating rate)
Power consumption	P_D	—	300	mW	
Operating temperature	T_A	–40	+85	°C	
Storage temperature	Tstg	–55	+150	°C	

Precautions: Permanent device damage may occur if the above “Absolute Maximum Ratings” are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

2. Recommended Operating Conditions

($AV_{SS} = V_{SS} = 0.0$ V)

Parameter	Symbol	Value		Unit	Remarks	
		Min.	Max.			
Power supply voltage	V_{CC} AV_{CC}	2.7*	3.6	V	Operation assurance range	MB89PV490, MB89F499
		2.2*	3.6	V	Operation assurance range	MB89497, MB89498
		1.5	3.6	V	Retains the RAM state in stop mode	
	AVR	2.7	3.6	V		
LCD power supply voltage	V1 to V3	Vss	Vcc	V		
Operating temperature	T_A	–40	+85	°C		

* : These values depend on the operating conditions and the analog assurance range. See Figure 1, 2 and "5. A/D Converter Electrical Characteristics."

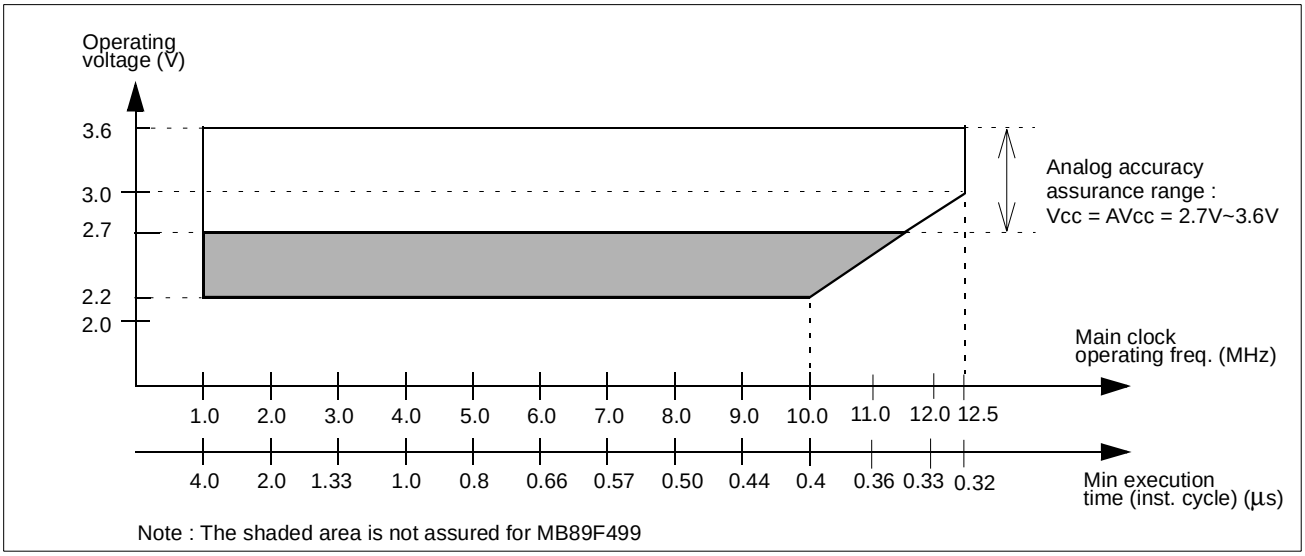


Figure 1 Operating Voltage vs. Main Clock Operating Frequency (MB89F499/497/498)

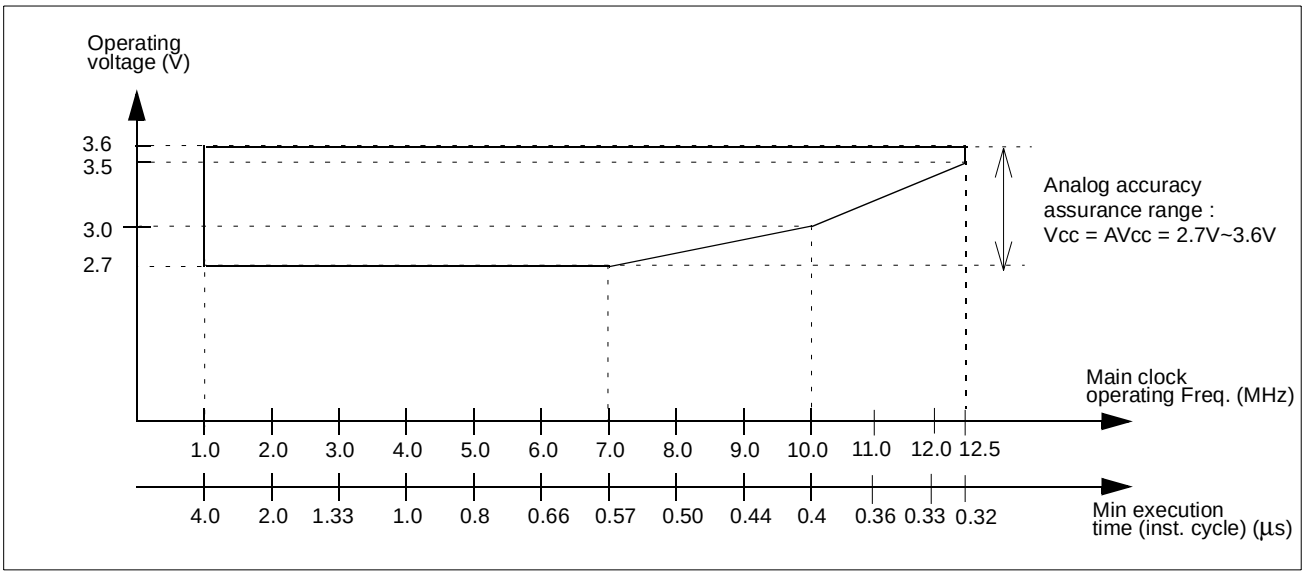


Figure 2 Operating Voltage vs. Main Clock Operating Frequency (MB89PV490)

Figure 1 and 2 indicate the operating frequency of the external oscillator at an instruction cycle of $4/F_{CH}$.

Since the operating voltage range is dependent on the instruction cycle, see minimum execution time if the operating speed is switched using a gear.

3. DC Characteristics

(AV_{CC} = V_{CC} = 3.0 V, AV_{SS} = V_{SS} = 0.0 V, T_A = –40°C to +85°C)

Parameter	Symbol	Pin	Condition	Value			Unit	Remarks
				Min.	Typ.	Max.		
"H" level input voltage	V_{IH}	P00 ~ P07, P10 ~ P17, P20 ~ P27, P30 ~ P37, P50 ~ P54, P60 ~ P67, P70 ~ P77, P80 ~ P84, SCL, SDA, MOD1, MOD2	—	0.7 V_{CC}	—	V_{CC} + 0.3	V	
		P40 ~ P47	—	0.7 V_{CC}	—	V_{SS} + 6.0	V	MB89PV490, MB89497/498
			—	0.7 V_{CC}	—	V_{SS} + 5.5	V	MB89F499
	V_{IHS}	$\overline{RST}$, MOD0, EC0, EC1, SCK0, SI0, SCK1, SI1, RMC, INT00 ~ INT07	—	0.8 V_{CC}	—	V_{CC} + 0.3	V	
	V_{IHA}	$\overline{INT10}$ ~ $\overline{INT17}$	—	0.85 V_{CC}	—	V_{CC} + 0.3	V	
"L" level input voltage	V_{IL}	P00 ~ P07, P10 ~ P17, P20 ~ P27, P30 ~ P37, P40 ~ P47, P50 ~ P54, P60 ~ P67, P70 ~ P77, P80 ~ P84, SCL, SDA, MOD1, MOD2	—	V_{SS} – 0.3	—	0.3 V_{CC}	V	
	V_{ILS}	$\overline{RST}$, MOD0, EC0, EC1, SCK0, SI0, SCK1, SI1, RMC, INT00 ~ INT07	—	V_{SS} – 0.3	—	0.2 V_{CC}	V	
	V_{ILA}	$\overline{INT10}$ ~ $\overline{INT17}$	—	V_{SS} – 0.3	—	0.5 V_{CC}	V	
Open-drain output pin application voltage	V_D	P40 ~ P47	—	V_{SS} – 0.3	—	V_{SS} + 6.0	V	MB89PV490, MB89497/498
			—	V_{SS} – 0.3	—	V_{SS} + 5.5	V	MB89F499
"H" level output voltage	V_{OH}	P10 ~ P17, P20 ~ P27, P30 ~ P37, P50 ~ P54, P60 ~ P67, P70 ~ P77, P80 ~ P82	I_{OH} = -2.0 mA	2.2	—	—	V	
		P00 ~ P07	I_{OH} = -4.0 mA	2.2	—	—	V	

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Parameter	Symbol	Pin	Condition	Value			Unit	Remarks
				Min.	Typ.	Max.		
"L" level output voltage	V_{OL}	P10 ~ P17, P20 ~ P27, P30 ~ P37, P50 ~ P54, P60 ~ P67, P70 ~ P77, P80 ~ P82, $\overline{RST}$	I_{OL} = 4.0 mA	—	—	0.4	V	
		P00 ~ P07	I_{OL} = 12.0 mA	—	—	0.4	V	
		P40 ~ P47	I_{OL} = 15.0 mA	—	—	0.4	V	
Input leakage current	I_{LI}	P00 ~ P07, P10 ~ P17, P20 ~ P27, P30 ~ P37, P40 ~ P47, P50 ~ P54, P60 ~ P67, P70 ~ P77, P80 ~ P84	0.45 V < V_I < V_{CC}	–5	—	+5	µA	Without pull-up resistor
Open-drain output leakage current	I_{LOD}	P40 ~ P47	0.0 V < V_I < V_{CC}	–5	—	+5	µA	
Pull-down resistance	R_{DOWN}	MOD0	V_I = V_{CC}	25	50	100	kΩ	Except MB89F499
Pull-up resistance	R_{PULL}	P00 ~ P07, P10 ~ P17, P20 ~ P27, P30 ~ P37, P50 ~ P54, P60 ~ P67, P70 ~ P77, P80 ~ P82, $\overline{RST}$	V_I = 0.0 V	25	50	100	kΩ	When pull-up resistor is selected (except $\overline{RST}$)
Common output impedance	R_{VCOM}	COM0 to COM3	V1 to V3 = +3.0 V	—	—	2.5	kΩ	
Segment output impedance	R_{VSEG}	SEG0 to SEG31	V1 to V3 = +3.0 V	—	—	15	kΩ	
LCD divided resistance	R_{LCD}	—	Between V_{CC} and V_{SS}	300	500	750	kΩ	
LCD controller/ driver leakage current	I_{LCDL}	V1 to V3, COM0 to COM3, SEG0 to SEG31	—	-1	—	+1	µA	

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Parameter	Symbol	Pin	Condition	Value			Unit	Remarks
				Min.	Typ.	Max.		
Power supply current	I_{CC1}	V_{CC}	F_{CH} = 10 MHz t_{inst} = 0.4 µs Main clock run mode	—	3.5	TBD	mA	MB89PV490, MB89497/498
				—	6.0	TBD	mA	MB89F499
	I_{CC2}		F_{CH} = 10 MHz t_{inst} = 6.4 µs Main clock run mode	—	0.4	TBD	mA	MB89PV490, MB89497/498
				—	1.5	TBD	mA	MB89F499
	I_{CCS1}		F_{CH} = 10 MHz t_{inst} = 0.4 µs Main clock sleep mode	—	1.2	TBD	mA	MB89PV490, MB89497/498
				—	2.0	TBD	mA	MB89F499
	I_{CCS2}		F_{CH} = 10 MHz t_{inst} = 6.4 µs Main clock sleep mode	—	0.4	TBD	mA	MB89PV490, MB89497/498
				—	1.0	TBD	mA	MB89F499
	I_{CCL}		F_{CL} = 32.768 kHz Sub-clock mode T_A = +25°C	—	22.0	TBD	µA	MB89PV490, MB89497/498
				—	35.0	TBD	µA	MB89F499
	I_{CCLPLL}		F_{CL} = 32.768 kHz Sub-clock mode T_A = +25°C sub PLL x 4	—	120.0	TBD	µA	MB89PV490, MB89497/498
				—	150.0	TBD	µA	MB89F499
	I_{CCLS}		F_{CL} = 32.768 kHz Sub-clock sleep mode T_A = +25°C	—	7.0	TBD	µA	MB89PV490, MB89497/498
				—	15.0	TBD	µA	MB89F499
	I_{CCT}		F_{CL} = 32.768 kHz Watch mode Main clock stop mode T_A = +25°C	—	1.0	TBD	µA	MB89PV490, MB89497/498
				—	5.0	TBD	µA	MB89F499
	I_{CCH}		T_A = +25°C Sub-clock stop mode	—	0.8	TBD	µA	MB89PV490, MB89497/498
				—	1.0	TBD	µA	MB89F499
	I_A	AV_{cc}	AV_{cc} = 3.0 V, T_A = +25°C	—	1.0	3.0	mA	A/D converting
	I_{AH}		T_A = +25°C	—	0.8	4.0	µA	A/D stop
Input capacitance	C_{IN}	Other than V_{CC}, V_{SS}, AV_{CC}, AV_{SS}, AVR	f = 1 MHz	—	10.0	—	pF	

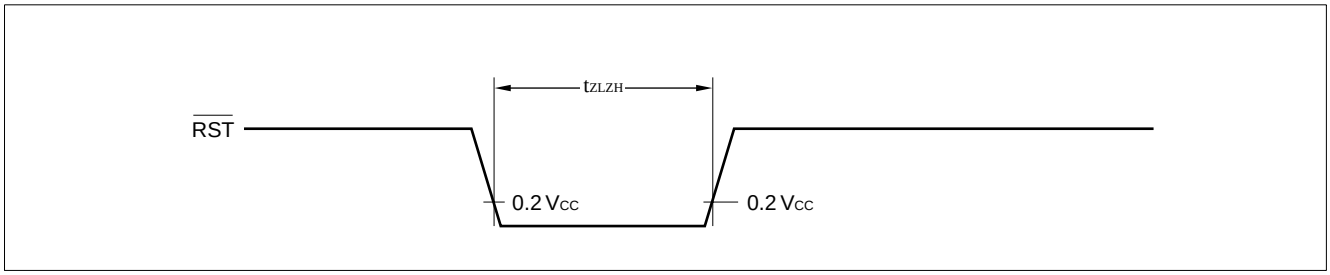
4. AC Characteristics

(1) Reset Timing

(AV_{CC} = V_{CC} = 3.0 V, AV_{SS} = V_{SS} = 0.0 V, T_A = –40°C to +85°C)

Parameter	Symbol	Condition	Value		Unit	Remarks
			Min.	Max.		
$\overline{RST}$ "L" pulse width	t_{ZLZH}	—	48 t_{HCYL}	—	ns	

Note: t_{HCYL} is the oscillation cycle ($1/F_{CH}$) to input to the X0 pin.
The MCU operation is not guaranteed when the "L" pulse width is shorter than t_{ZLZH}.

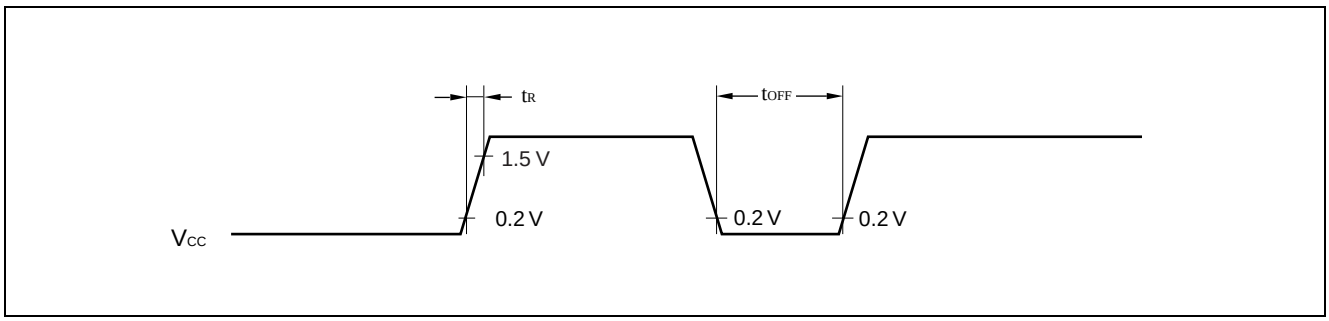


(2) Power-on Reset

(AV_{SS} = V_{SS} = 0.0 V, T_A = –40°C to +85°C)

Parameter	Symbol	Condition	Value		Unit	Remarks
			Min.	Max.		
Power supply rising time	t_R	—	—	50	ms	
Power supply cut-off time	t_{OFF}		1	—	ms	Due to repeated operations

Note: Make sure that power supply rises within the selected oscillation stabilization time.
Rapid changes in power supply voltage may cause a power-on reset. If power supply voltage needs to be varied in the course of operation, a smooth voltage rise is recommended.

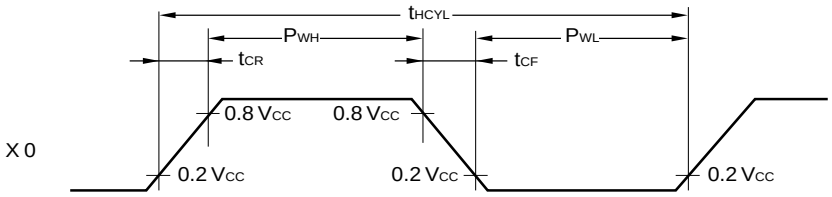


(3) Clock Timing

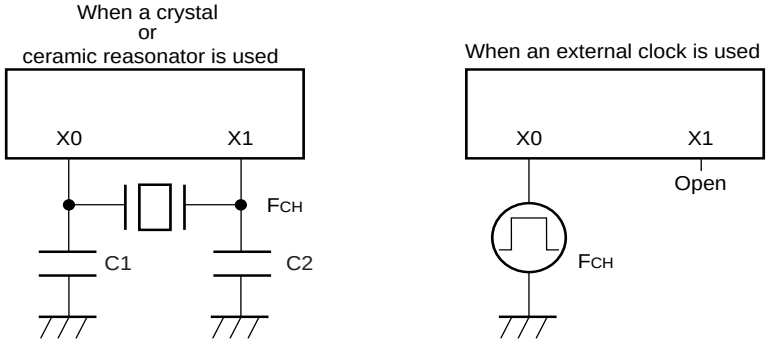
(AV_{SS} = V_{SS} = 0.0 V, T_A = –40°C to +85°C)

Parameter	Symbol	Pin	Value			Unit	Remarks
			Min.	Typ.	Max.		
Clock frequency	F_{CH}	X0, X1	1	—	12.5	MHz	
	F_{CL}	X0A, X1A	—	32.768	75	kHz	
Clock cycle time	t_{HCYL}	X0, X1	80	—	1000	ns	
	t_{LCYL}	X0A, X1A	13.3	30.5	—	µs	
Input clock pulse width	P_{WH} P_{WL}	X0	20	—	—	ns	External clock
	P_{WHL} P_{WLL}	X0A	—	15.2	—	µs	
Input clock rising/falling time	t_{CR} t_{CF}	X0, X0A	—	—	10	ns	

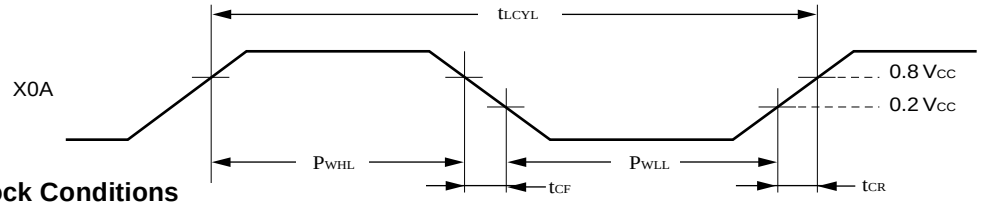
X0 and X1 Timing and Conditions



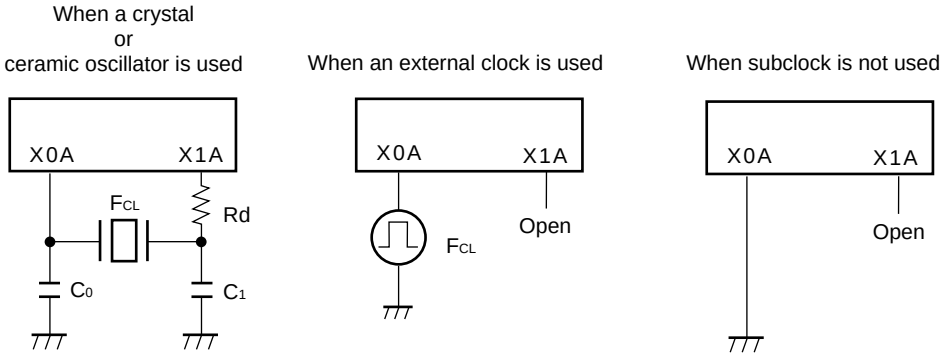
Main Clock Conditions



Sub-clock Timing and Conditions



Sub-clock Conditions

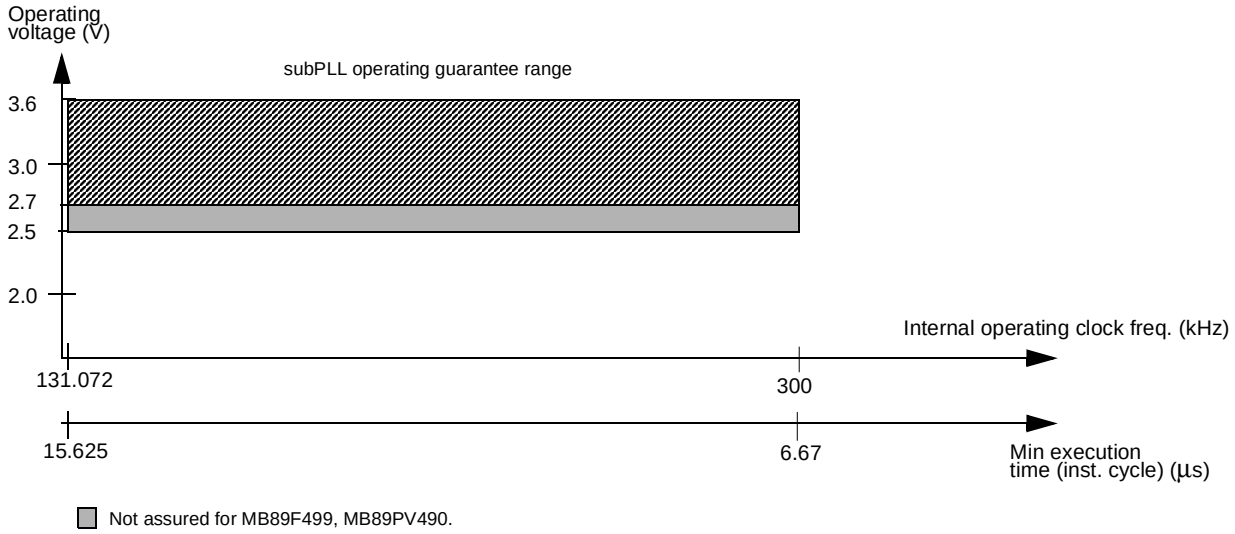


(4) Instruction Cycle

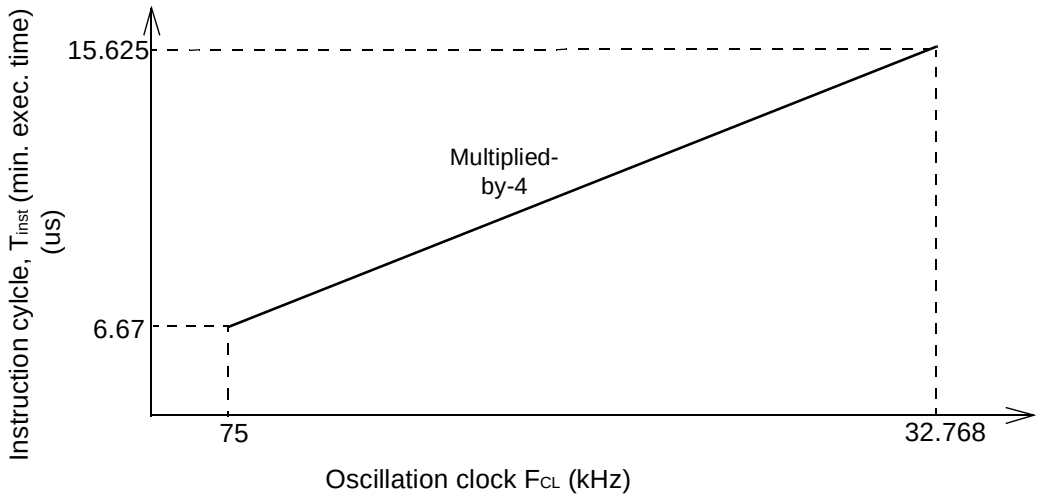
Parameter	Symbol	Value	Unit	Remarks
Instruction cycle (minimum execution time)	t_{inst}	$4/F_{CH}$, $8/F_{CH}$, $16/F_{CH}$, $64/F_{CH}$	µs	$(4/F_{CH})t_{inst}$ = 0.32 µs when operating at F_{CH} = 12.5 MHz
		$2/F_{CL}$, $1/2F_{CL}$	µs	$(2/F_{CL})t_{inst}$ = 61.036 µs when operating at F_{CL} = 32.768 kHz

- PLL operation guarantee range (subPLL x 4)

Relationship between internal operating clock frequency and power supply voltage



Relationship between subclock oscillating frequency and instruction cycle when subPLL is enabled



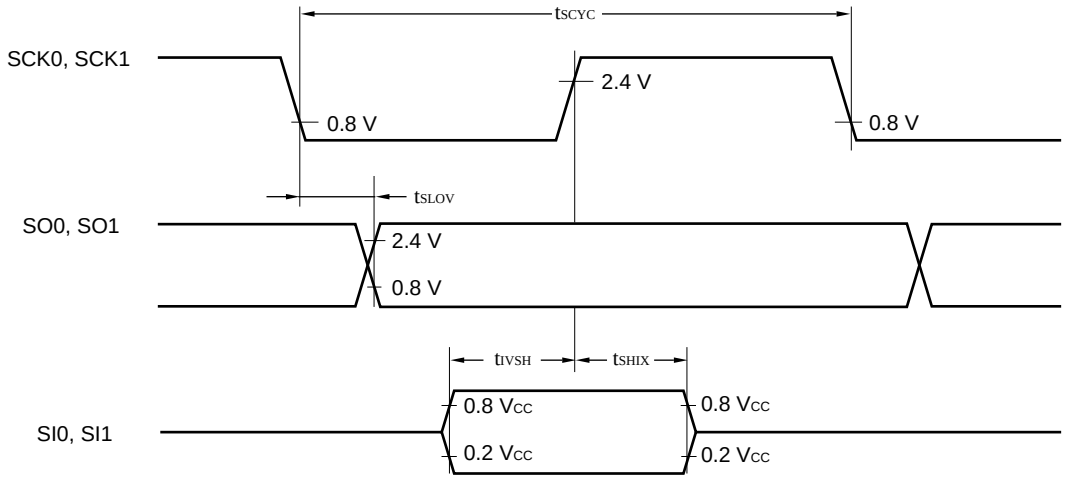
(5) Serial I/O Timing

(AV_{CC} = V_{CC} = 3.0 V, AV_{SS} = V_{SS} = 0.0 V, T_A = –40°C to +85°C)

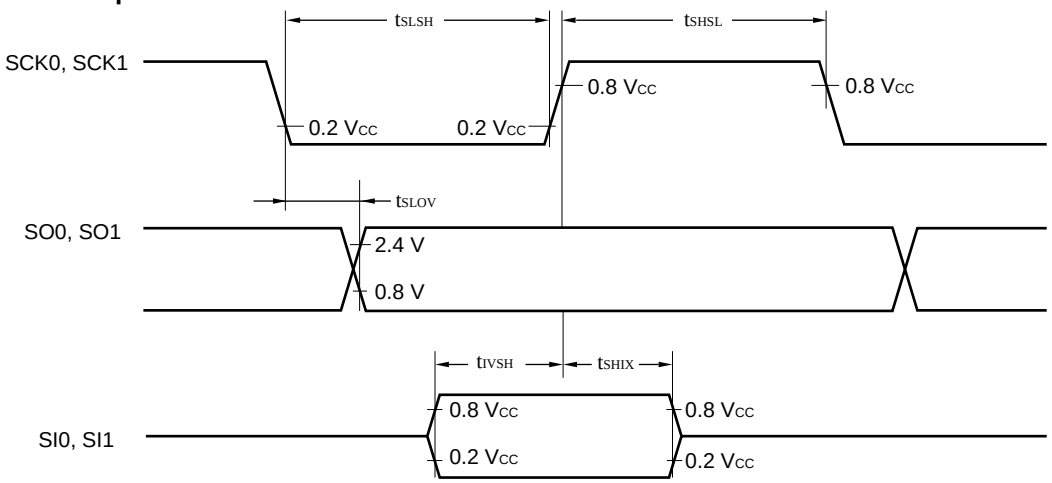
Parameter	Symbol	Pin	Condition	Value		Unit
				Min.	Max.	
Serial clock cycle time	t_{SCYC}	SCK0, SCK1	Internal shift clock mode	2 t_{inst}*	—	µs
SCK ↓ → SO time	t_{SLOV}	SCK0, SCK1, SO0, SO1		–200	200	ns
Valid SI → SCK ↑	t_{IVSH}	SI0, SI1, SCK0, SCK1		1/2 t_{inst}*	—	µs
SCK ↑ → valid SI hold time	t_{SHIX}	SCK0, SCK1, SI0, SI1		1/2 t_{inst}*	—	µs
Serial clock “H” pulse width	t_{SHSL}	SCK0, SCK1	External shift clock mode	1 t_{inst}*	—	µs
Serial clock “L” pulse width	t_{SLSH}			1 t_{inst}*	—	µs
SCK ↓ → SO time	t_{SLOV}	SCK0, SCK1, SO0, SO1		0	200	ns
Valid SI → SCK ↑	t_{IVSH}	SI0, SI1, SCK0, SCK1		1/2 t_{inst}*	—	µs
SCK ↑ → valid SI hold time	t_{SHIX}	SCK0, SCK1, SI0, SI1		1/2 t_{inst}*	—	µs

* : For information on t_{inst}, see “(4) Instruction Cycle.”

Internal Clock Operation



External Clock Operation



(6) I²C Timing

(Vcc = 3.0V, AV_{SS} = V_{SS} = 0.0 V, T_A = –40°C to +85°C)

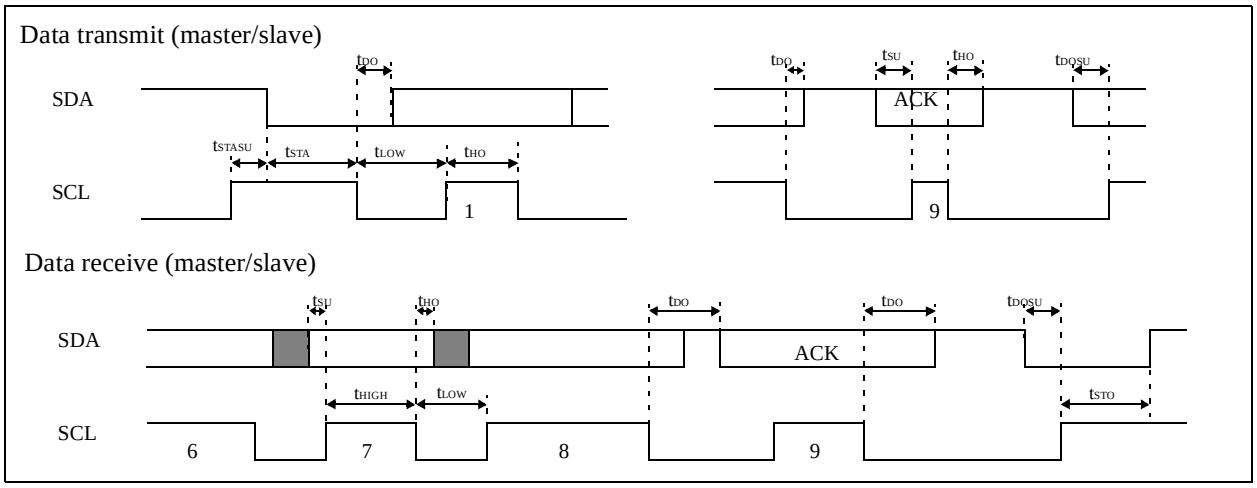
Parameter	Symbol	Pin	Condition	Value		Unit	Remarks
				Min.	Max.		
Start condition output	t_{STA}	SCL SDA		$1/4t_{inst}$*1 x M x N - 20	$1/4t_{inst}$ x M x N + 20	ns	master mode
Stop condition output	t_{STO}	SCL SDA		$1/4t_{inst}$ x (M x N + 8) - 20	$1/4t_{inst}$ x (M*2 x N*3 + 8) + 20	ns	master mode
Start condition detect	t_{STA}	SCL SDA		$1/4t_{inst}$ x 6 + 40	—	ns	
Stop condition detect	t_{STO}	SCL SDA		$1/4t_{inst}$ x 6 + 40	—	ns	
Re-start condition output	t_{STASU}	SCL SDA		$1/4t_{inst}$ x (M x N + 8) - 20	$1/4t_{inst}$ x (M x N + 8) + 20	ns	master mode
Re-start condition detect	t_{STASU}	SCL SDA		$1/4t_{inst}$ x 4 + 40	—	ns	
SCL output LOW width	t_{LOW}	SCL		$1/4t_{inst}$ x M x N - 20	$1/4t_{inst}$ x M x N + 20	ns	master mode
SCL output HIGH width	t_{HIGH}	SCL		$1/4t_{inst}$ x (M x N + 8) - 20	$1/4t_{inst}$ x (M x N + 8) + 20	ns	master mode
SDA output delay	t_{DO}	SDA		$1/4t_{inst}$ x 4 - 20	$1/4t_{inst}$ x 4 + 20	ns	
SDA output setup time after interrupt	t_{DOSU}	SDA		$1/4t_{inst}$ x 4 - 20	—	ns	*4
SCL input LOW pulse width	t_{LOW}	SCL		$1/4t_{inst}$ x 6 + 40	—	ns	
SCL input HIGH pulse width	t_{HIGH}	SCL		1/4 t_{inst} x 2 + 40	—	ns	
SDA input setup time	t_{SU}	SDA		40	—	ns	
SDA hold time	t_{HO}	SDA		0	—	ns	

*1: For information in t_{inst}, see "(4) Instruction Cycle".

*2: M is defined in the ICCR CS4 and CS3 (bit 4 to bit 3). For details, please refer to the H/W manual register explanation.

*3: N is defined in the ICCR CS2 to CS0 (bit 2 to bit 0)

*4: When the interrupt period is grater than SCL "L" width, SDA and SCL output (Standard) value is based on hypothesis when rising time is 0 ns.

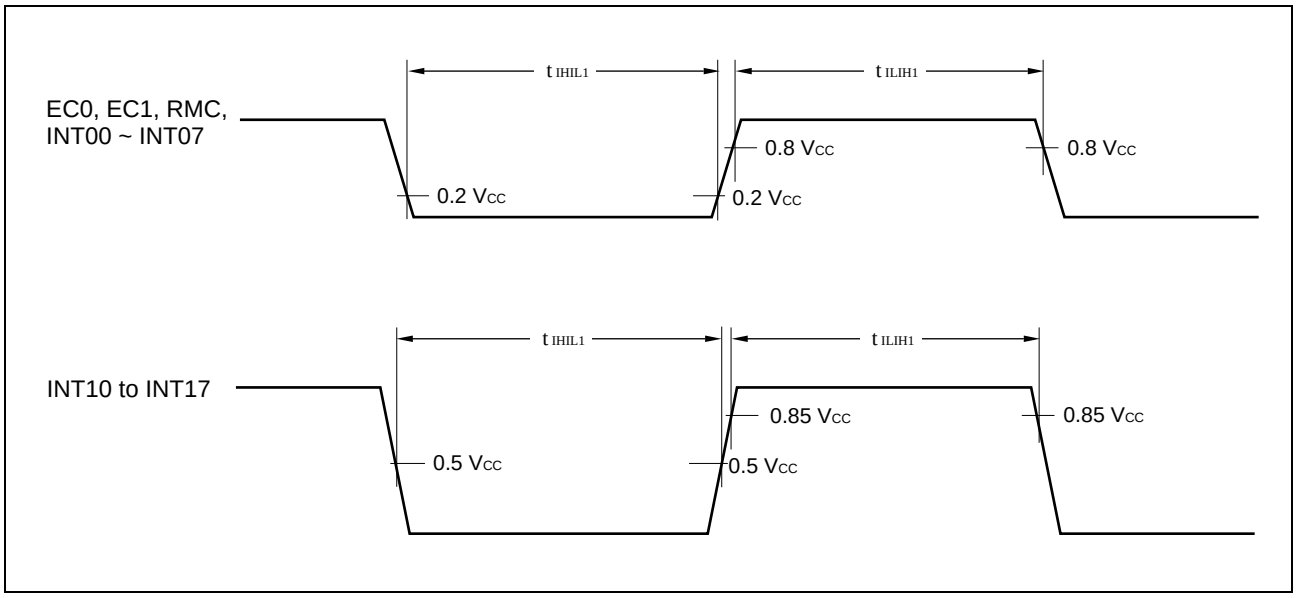


(7) Peripheral Input Timing

(AV_{CC} = V_{CC} = 3.0 V, AV_{SS} = V_{SS} = 0.0 V, T_A = –40°C to +85°C)

Parameter	Symbol	Pin	Value		Unit	Remarks
			Min.	Max.		
Peripheral input “H” pulse width 1	t_{ILIH1}	EC0, EC1, RMC, INT00 ~ INT07, INT10 ~ INT17	2 t_{inst}*	—	µs	
Peripheral input “L” pulse width 1	t_{IHIL1}		2 t_{inst}*	—	µs	

* : For information on t_{inst}, see “(4) Instruction Cycle.”



5. A/D Converter Electrical Characteristics

(1) A/D Converter Electrical Characteristics

($AV_{CC} = V_{CC} = 2.7$ V ~ 3.6 V, $AV_{SS} = V_{SS} = 0.0$ V, $T_A = -40°C$ to $+85°C$)

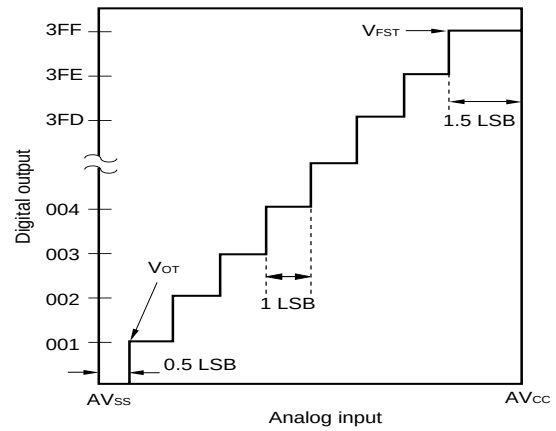
Parameter	Symbol	Pin	Value			Unit	Remarks
			Min.	Typ.	Max.		
Resolution	—	—	—	10	—	bit	
Total error			—	—	±3.0	LSB	
Linearity error			—	—	±2.5	LSB	
Differential linearity error			—	—	±1.9	LSB	
Zero transition voltage	V_{OT}		AV_{SS} – 1.5 LSB	AV_{SS} + 0.5 LSB	AV_{SS} + 2.5 LSB	mV	
Full-scale transition voltage	V_{FST}		AV_{CC} – 3.5 LSB	AV_{CC} – 1.5 LSB	AV_{CC} - 0.5 LSB	mV	
A/D mode conversion time	—		—	—	38 tinst*	µs	
Analog port input current	I_{AIN}	AN0 to AN7	—	—	10	µA	
Analog input voltage	V_{AIN}		AV_{SS}	—	AVR	V	
Reference voltage	—	AVR	AV_{SS} + 2.7	—	AV_{CC}	V	
Reference voltage supply current	I_R		—	200	TBD	µA	A/D is activated
	I_{RH}		—	—	5	µA	A/D is stopped

* : For information on t_{inst}, see "(4) Instruction Cycle" in "4. AC Characteristics".

(2) A/D Converter Glossary

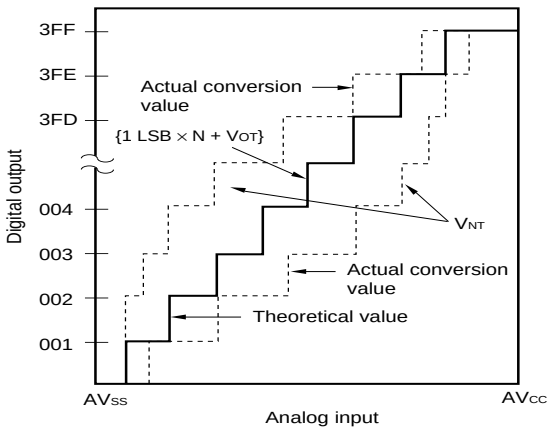
- Resolution
  Analog changes that are identifiable with the A/D converter.
  When the number of bits is 10, analog voltage can be divided into $2^{10} = 1024$.
- Linearity error (unit: LSB)
  The deviation of the straight line connecting the zero transition point ("00 0000 0000" ↔ "00 0000 0001") with the full-scale transition point ("11 1111 1111" ↔ "11 1111 1110") from actual conversion characteristics.
- Differential linearity error (unit: LSB)
  The deviation of input voltage needed to change the output code by 1 LSB from the theoretical value.
- Total error (unit: LSB)
  The difference between theoretical and actual conversion values.

Theoretical I/O characteristics



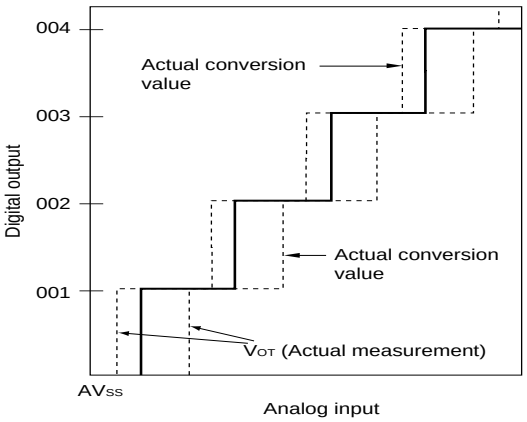
$$1\ \text{LSB} = \frac{V_{FST} - V_{OT}}{1022}\ (\text{V})$$

Total error

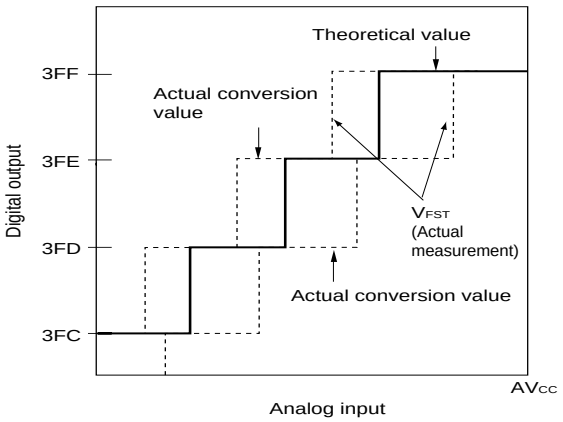


$$\text{Total error} = \frac{V_{NT} - \{1\ \text{LSB} \times N + 0.5\ \text{LSB}\}}{1\ \text{LSB}}$$

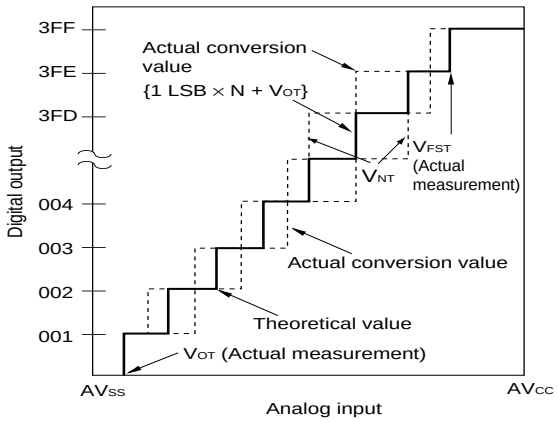
Zero transition error



Full-scale transition error

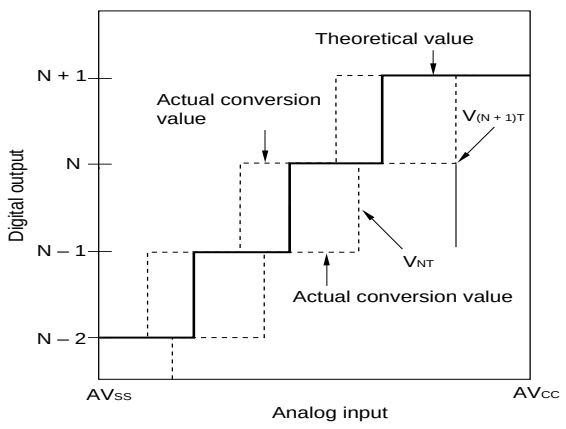


Linearity error



$$\text{Linearity error} = \frac{V_{NT} - \{1\ \text{LSB} \times N + V_{OT}\}}{1\ \text{LSB}}$$

Differential linearity error



$$\text{Differential linearity error} = \frac{V_{(N+1)T} - V_{NT}}{1\ \text{LSB}} - 1$$

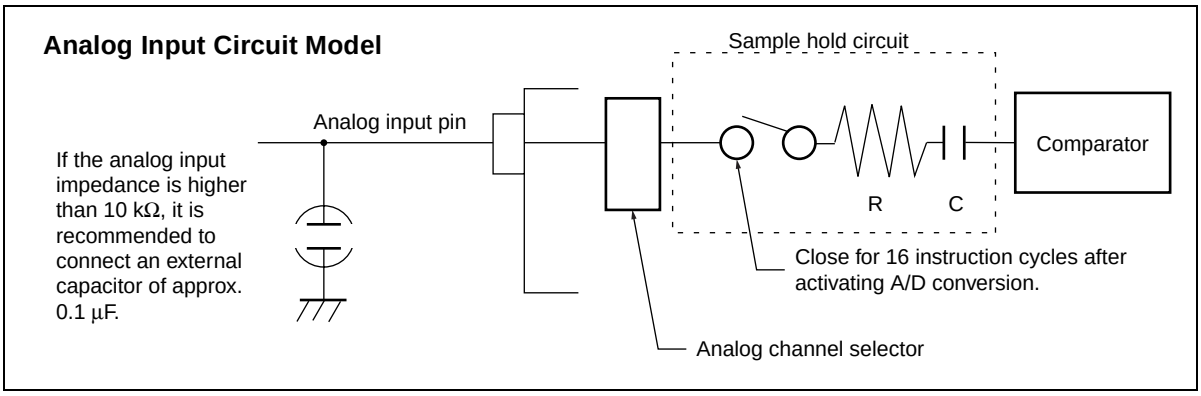
(3) Notes on Using A/D Converter

- Input impedance of the analog input pins
  The A/D converter used for the MB89490 series contains a sample and hold circuit as illustrated below to fetch analog input voltage into the sample and hold capacitor for 16 instruction cycles after activation A/D conversion.

  For this reason, if the output impedance of the external circuit for the analog input is high, analog input voltage might not stabilize within the analog input sampling period. Therefore, it is recommended to keep the output impedance of the external circuit low.

  Note that if the impedance cannot be kept low, it is recommended to connect an external capacitor of about 0.1 μF for the analog input pin.

Analog Input Circuit Model



	MB89F499	MB89PV490/MB89497/MB89498
R: analog input equivalent resistance	2.4 kΩ	2.4 kΩ
C: analog input equivalent capacitance	52 pF	53 pF

■ MASK OPTIONS

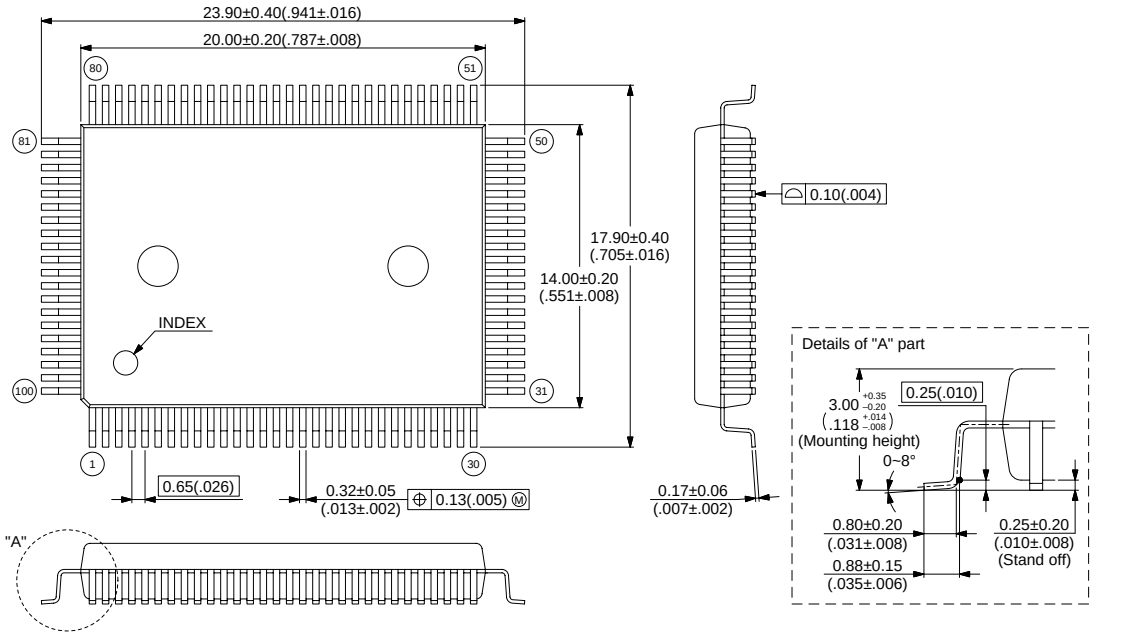
No.	Part number	MB89497	MB89498	MB89F499	MB89PV490
	Specifying procedure	Specify when ordering mask		Setting not possible	
1	Selection of oscillation stabilization time (OSC) • The initial value of the oscillation stabilization time for the main clock can be set by selecting the values of the WTM1 and WTM0 bit on the right.	Selectable OSC 1 : $2^{10}/F_{CH}$ 2 : $2^{14}/F_{CH}$ 3 : $2^{18}/F_{CH}$		Fixed to oscillation stabilization time of $2^{18}/F_{CH}$	

■ ORDERING INFORMATION

Part number	Package	Remarks
MB89497PF MB89498PF MB89F499PF	100-pin Plastic QFP (FPT-100P-M06)	
MB89PV490CF	100-pin Ceramic MQFP (MQP-100C-P01)	

■ PACKAGE DIMENSIONS

100-pin Plastic QFP
FPT-100P-M06



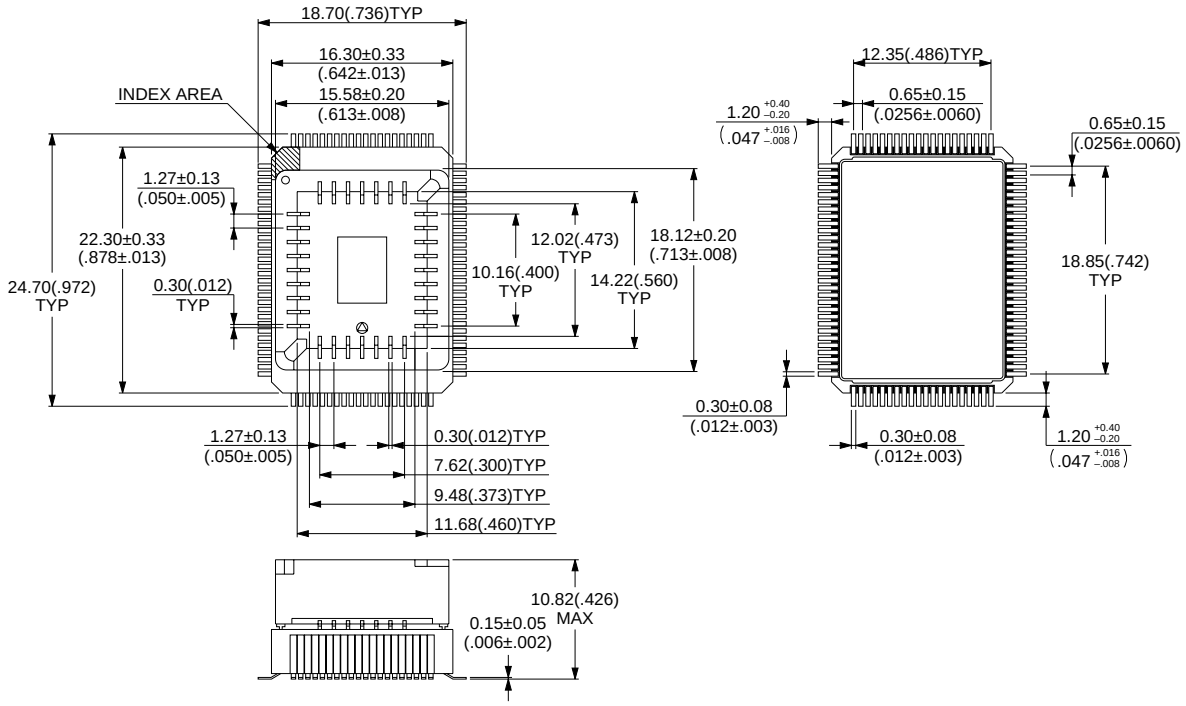
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Dimensions in mm (inches)

(Continued)

(Continued)

100-pin ceramic MQFP
MQP-100C-P01



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MEMO

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